

Application manual

Real Time Clock Module

RX8130CE

ETM50E-07

Product name	Product number
RX8130CE	X1B000311000100

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ETM50E Revision History

Rev. No.	Date	Page	Description
01	---	---	---
02	2015/10/05		Release
03	2016/5/10	1	Corrected a the block diagram.
		4	Add description to [3.2. Pin Functions].
		9	Corrected a [10.1. Characteristic for the fluctuation of the power supply]
		13	Corrected a [7) Clock output function]
		27	Corrected a [14.7.2. Related register of Battery backup switchover function]
04	2016/9/20	3	Updated the Recommended soldering pattern. Optimization of the text.
05	2016/1/23	2	Added terminal processing when output terminal is not used.
		3	Added typical value of external dimensions.
		3	Added recommended soldering pattern.
		6	Corrected Max. value of High- Level input voltage.
		8	Corrected reset delay time (at recovery form backup).
		9	Corrected access wait time.
		20	Changed 7) TSTP bit related table.
		21	Added timer circuit block diagram
		25	Added alarm circuit block diagram
		27	Added time update circuit block diagram
		30	Corrected table operation stages of voltage detection.
		36	Added comment to wait time.
		37	Added comments related to STOP bit in 3)The setting of the clock and calendar.
06	2019/7/31	42	Added address circulation table of auto increment function. -06 31 Jul 2019 5 Added Figure 4-4. Circuit EX4.
		5	Added Figure 4-4. Circuit EX4.
		9	Added Figure 9-1,9-2,9-3 Re-chargeable battery current
		17	Corrected Table 13-1. Register table (expression Z)
		20	Added Figure 14-1. Basic (32kHz oscillation, counter, FOUT) Function
		32 to 41	Fully revised (battery Backup switching)
		40	Reference characteristics of the charge current in VBAT.
		53	Added Figure 14-33. Typical MCU connection
		53	Added Figure 14-34 32kHz oscillator connection
		54	Added Tables
		55	Added Figures

07	2021/7/5	All	Table number. serialization
		All	Figure number. serialization
		All	The link to index was added to the all footer.
		7	Power supply connection , "VD" symbol was deleted. Ex: VD3.0 to 3.0 V
		9	Recommended Operation Condition As for interface voltage Min., Both spec mentioned, INIEN=0 and INIEN=1.
		14	Optimized this chapter structure 10. Interface timing when power is turned ON / OFF
		16	1) 2) The Power-On Chart was separated into two cases with and without battery. 3) Correction of errors of tF condition. Error: tF = -V _{DET1} from "V _{DD} OFF". Correct: tF = V _{CLK} from "V _{DD} OFF". 4) Addition that describes the risk of not satisfying tR / tF 5) Description of Table11 was updated.
		21	13.2.2. Register initial value Added description, that value are same in after software-Reset.
		39	1) Graph is added for the charge current to Battery. <i>Figure27 V_{BAT} charge current characteristics V_{DD} = 3.0 V, 5.5 V</i> 2) Charging circuit diagram is added for reference. <i>Figure 28 Re-chargeable battery connection</i>
		40	Renewed the description of INIEN-bit .
		46	Updated note of STOP-bit .
		48, 49	Charge enabled timing was fine corrected in Timing Chart. Figure 37 and Figure 38
		54	Software-Reset-Flow was added. Software-Reset .

55	INIEN bit processing was added to Flow-chart of initializing .
64	Pin connection was added for use as 32.768 kHz-Oscillator .

Table of contents

ETM50E Revision History	2
Table of contents	4
1. Overview.....	6
2. Block Diagram	6
3. Terminal description.....	7
3.1. Terminal connections.....	7
3.2. Pin Functions	7
4. Examples of external connection	8
4.1. Examples of power supply connection.....	8
5. External Dimensions / Marking Layout.....	9
6. Absolute Maximum Ratings	10
7. Recommended Operating Conditions	10
8. Frequency Characteristics	10
9. Electrical Characteristics	11
10. Interface timing when power is turned ON / OFF.....	15
10.1. Restrictions of I ² C-Bus interface in the initial power on.....	15
10.2. Precautions for power ON / OFF	15
10.3 V _{DD} ON / OFF when using power switching (INIEN = 1)	16
10.4 V _{DD} ON / OFF when power switching is not used (INIEN = 0)	16
11. Reference Information.....	17
12. Application Notes	18
13. Overview of Functions and Registers.....	19
13.1. Overview of Functions	19
13.2. Register Table	20
13.2.1. Register Table	20
13.2.2. Register initial value and Read/Write operation Table	21
13.3. Description of registers	22
13.3.1. Clock and calendar registers (0h ~ 16h).....	22
13.3.2. RAM registers (20h ~ 23h)	22
13.3.3. Alarm registers (17h ~ 19h)	22
13.3.4. Timer setting and Timer counter register for wakeup timer (1Ah ~ 1Eh)	22
13.3.5. Function-related register 1 (1Ch ~ 1Fh)	22
13.3.6. Function-related register 2 (1Fh).....	23
13.3.7. Digital offset register (30h)	23
14. Functions	24
14.1. Clock calendar explanation.....	24
14.1.1. Clock counter.....	24
14.1.2. Week counter	25
14.1.3. Calendar counter.....	25
14.2. Wakeup Timer Interrupt Function	26
14.2.1. Related registers for function of wakeup timer interrupt function	26
14.2.2. Wakeup timer start timing	29
14.2.3. Wakeup timer interrupt interval (example).....	30
14.2.4. Diagram of wakeup timer interrupt function	30
14.3. Alarm Interrupt Function	32
14.3.1. Related registers for Alarm interrupt functions.....	32
14.3.2. Examples of alarm settings	33
14.4. Time Update Interrupt Function	35
14.4.1. Related registers for time update interrupt functions.	35

14.4.2. Time update interrupt function diagram	36
14.5. Oscillation stop detection function	37
14.5.1. Related registers for Oscillation stop and Voltage low detect function.	37
14.6. FOUT function	37
14.6.1. FOUT control register.	37
14.6.2. FOUT function Table.	37
15 Battery backup switchover function.....	38
15.1. Description of Battery backup switchover function.....	38
15.2 Reference characteristics of switching elements.	38
15.3 Reference characteristics of the charge current	39
15.4 Re-Chargeable battery Voltage Current features	39
15.5. Related register of Battery backup switchover function	40
15.6 Detection voltage setting.....	45
15.7. Power supply control	47
15.8 Main power supply (V_{DD}) voltage and operation state (INIEN bit = 1).....	48
15.9. Backup power supply (V_{BAT}) voltage and a charge state	49
16. Reset output function	50
17. Digital offset function.....	51
17.1.Digital offset register	51
17.2. Effect of the digital offset function to other functions.....	52
18. Flow-chart.....	53
18.1 Initializing example	53
18.2 Software Reset	54
18.3 Example of Initialization routine	55
18.4 Example of Initialization routine (only clock usage)	56
18.5 The setting of the clock and calendar	56
18.6 The reading of the clock and calendar	57
18.7 Setting example of the wakeup timer interrupt function	57
18.8 Setting example of the Alarm interrupt function	58
19 Serial communication.....	59
19.1 Overview of I ² C-Bus Interface.....	59
19.2 Data transfers	59
19.3 Starting and stopping I ² C-Bus communications.....	59
19.4 Slave address	59
19.5 System configuration	60
19.6 I ² C-Bus protocol.....	61
20 Circuit Diagram connection	63
20.1 Typical MCU connection	63
20.2 32.768 kHz oscillator application connection.....	64
21. Tables.....	65
22. Figures.....	66
Contacts	68

Build-in backup battery charge control function SERIAL-INTERFACE REAL TIME CLOCK MODULE

RX8130 CE

- Built in frequency adjusted 32.768 kHz crystal unit.
- Interface type : I²C-Bus interface (up to 400 kHz)
- Wide operating voltage range : 1.6 V to 5.5 V
- Wide timekeeper voltage range : 1.1 V to 5.5 V
- Auto power switching function : Switchover by main power supply monitor.
- Backup battery charge control function : For rechargeable lithium batteries.
- Low leak current : A leak current from a backup power supply pin. 5nA Max.
- Reset function : At low supply voltage, external reset signal is generated.
- Low voltage detection : Supply voltage and backup voltage detection
- Time correction : Digital offset function
- The various function including full calendar, alarm, timer, etc.

1. Overview

RX8130CE is a real-time clock module of the I²C serial interface system, 32.768 kHz crystal and oscillator is built-in it. The real-time clock function incorporates not only a calendar and clock counter for the year, month, day, day of the week, hour, minute, and second, but also a time alarm, wakeup timer, and time update interruption, among other features. By the backup battery charge control function and the interface power supply input pin, RX8130CE can support various power supply circuitries. All these many functions are implemented in a thin, compact ceramic package, which makes it suitable for various kinds of small electronic devices, low power IoT devices etc.

2. Block Diagram

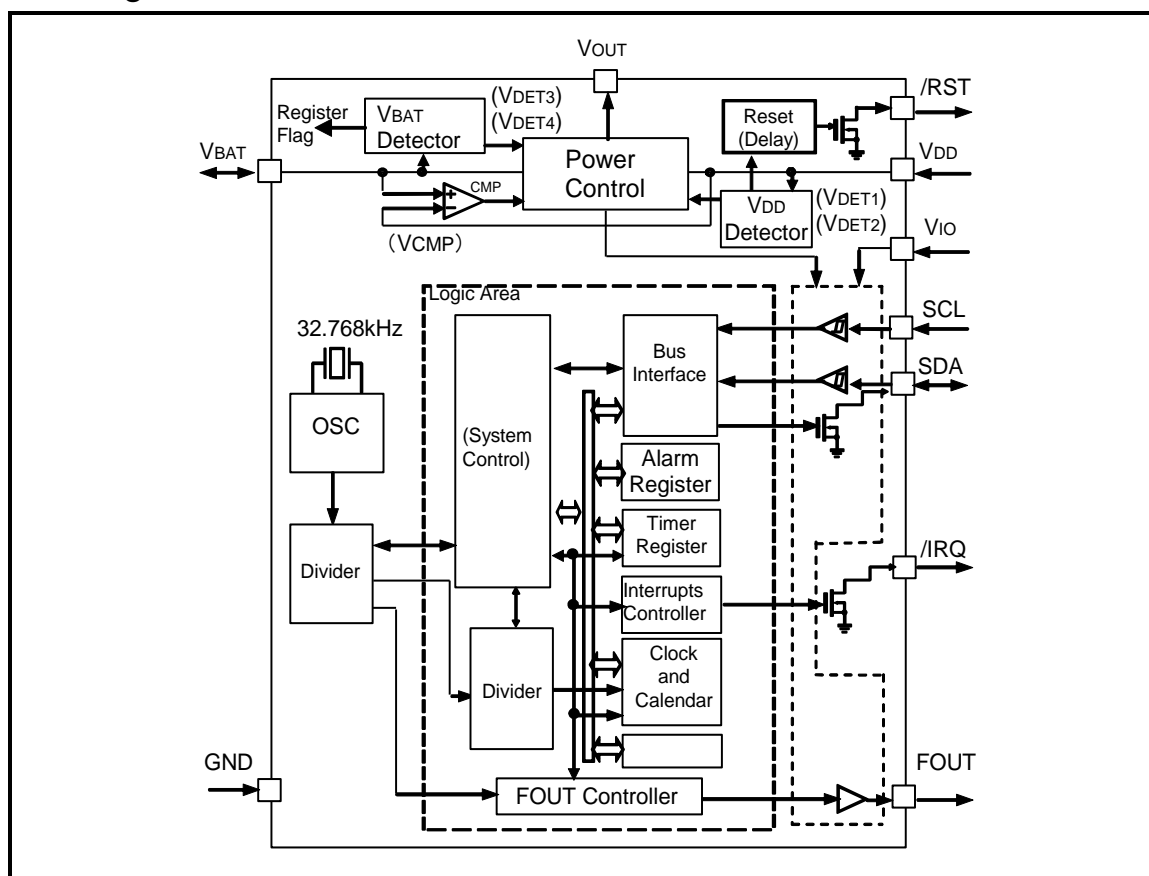


Figure 1 Block Diagram

3. Terminal description

3.1. Terminal connections

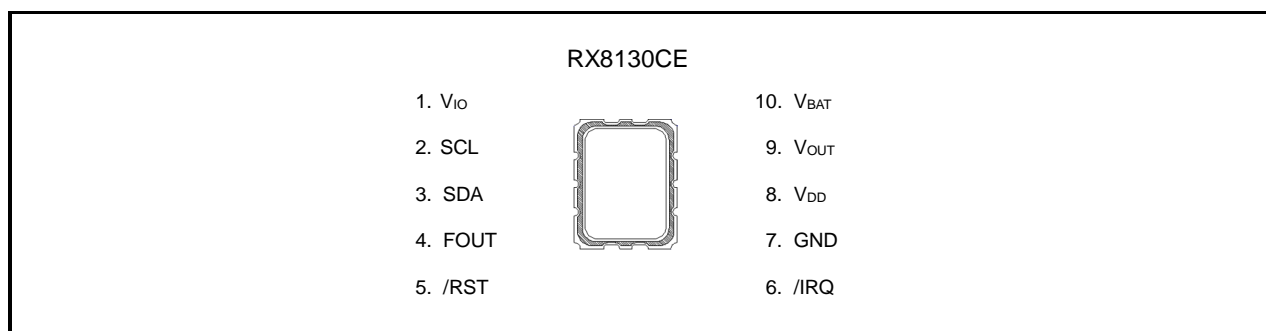


Figure 2 Package

3.2. Pin Functions

Table 1 Pin Description

Signal name	I/O	Function
SCL	Input	Serial clock input pin.
SDA	Bi-directional	Data input and output pin.
FOUT	Output	Frequency output pin with output control function. (CMOS) Output frequency can be selected as 32.768k Hz, 1024 Hz, 1 Hz.
/ RST	Output	Even in the backup mode, this pin can operate. In case of V_{DD} voltage drop detection, a reset signal is outputted. (N-ch open drain) In case of V_{DD} voltage rise detection, it releases the reset signal after 60ms.
/ IRQ	Output	Interrupt output by Alarm and Timer events.(N-ch open drain) This pin can output even a backup mode.
V_{DD}	–	This is a power-supply pin for the internal logic.
V_{IO}	–	This is an interface power supply pin. Connect the same power supply as the MCU.
V_{OUT}	–	Internal voltage output pin. Connect smoothing capacitor of 1.0uF
V_{BAT}	–	This is a power supply pin for backup battery. This is a pin to connect a large-capacity capacitor, a secondary battery, and a primary battery. In a backup mode, the voltage is supplied inside by this pin.
GND	–	Connected to a ground.

Note: Connect a bypass capacitor rated at least 0.1 μ F between power supply pins and GND pin.

Note: Input pins are able to input up to 5.5V regardless of V_{IO} applied voltage.

Note: Open drain pins are able to Pull-up to 5.5V regardless of V_{IO} applied voltage.

Note: Use the FOUT, /RST, /IRQ terminals as Open when not in use. Don't connected to GND or V_{DD}

4. Examples of external connection

4.1. Examples of power supply connection

(1) Case of different I/F voltage and charge voltage

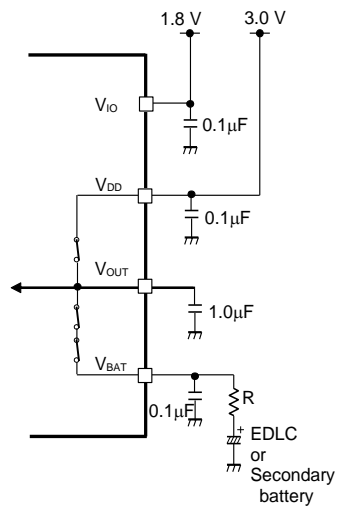


Figure 3 Circuit EX1

(2) Same I/F voltage and charge voltage (CHGEN=1, INIEN=1)

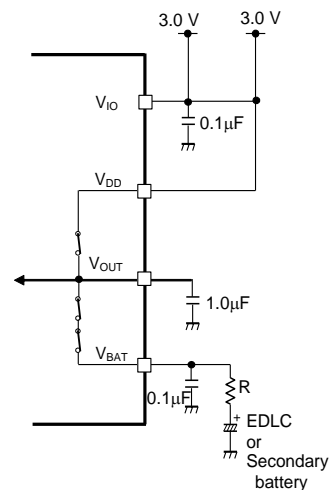


Figure 4 Circuit EX2

(3) Primary battery as backup (CHGEN=0)

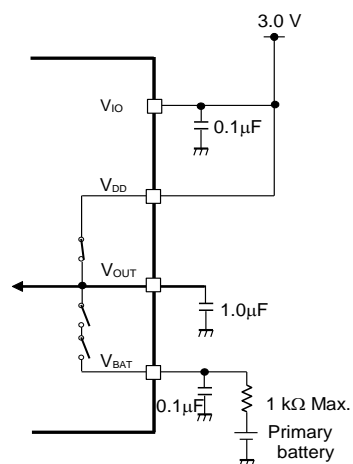


Figure 5 Circuit EX3

(4) Case of VDD supply only.

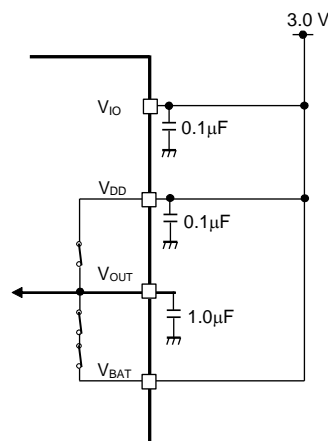


Figure 6 Circuit EX4

5. External Dimensions / Marking Layout

5.1. External Dimensions

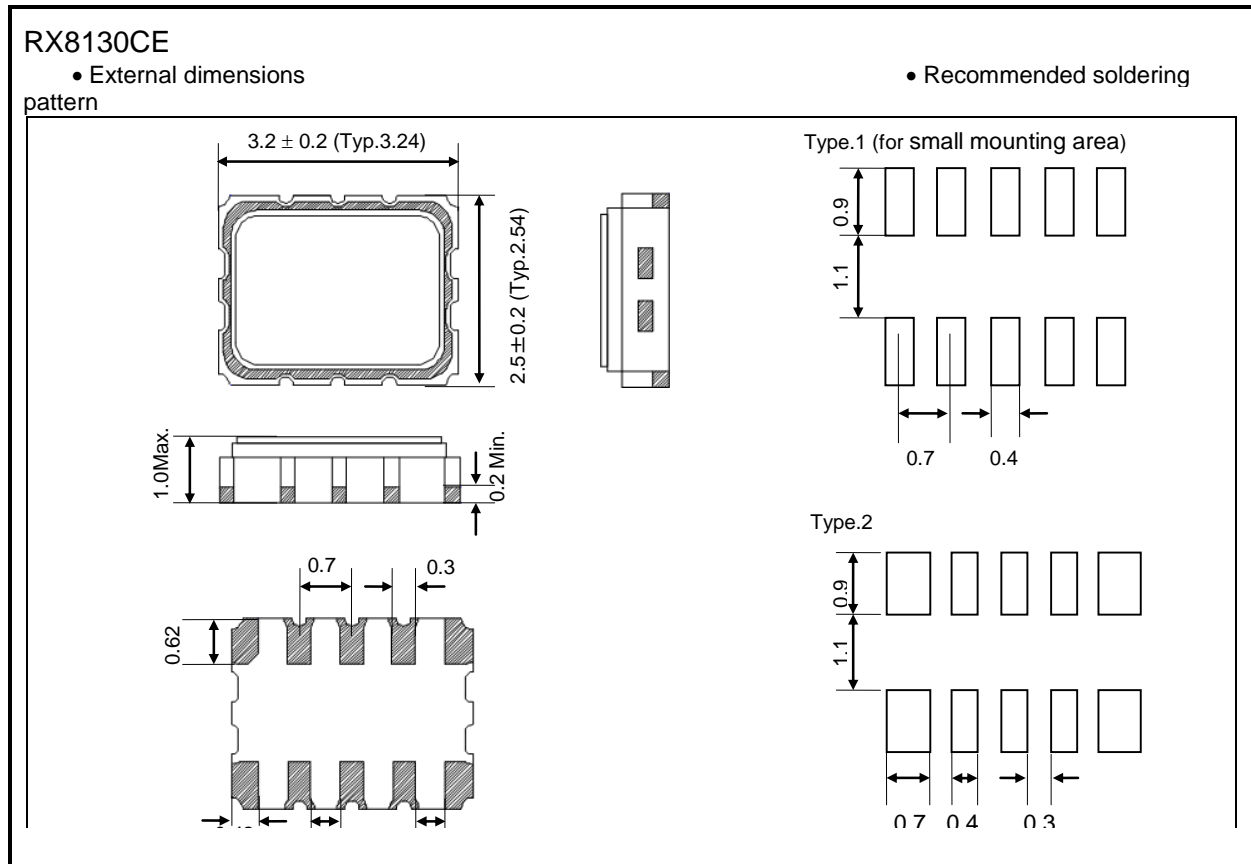


Figure 7 External Dimension and Soldering pattern

5.2. Marking Layout

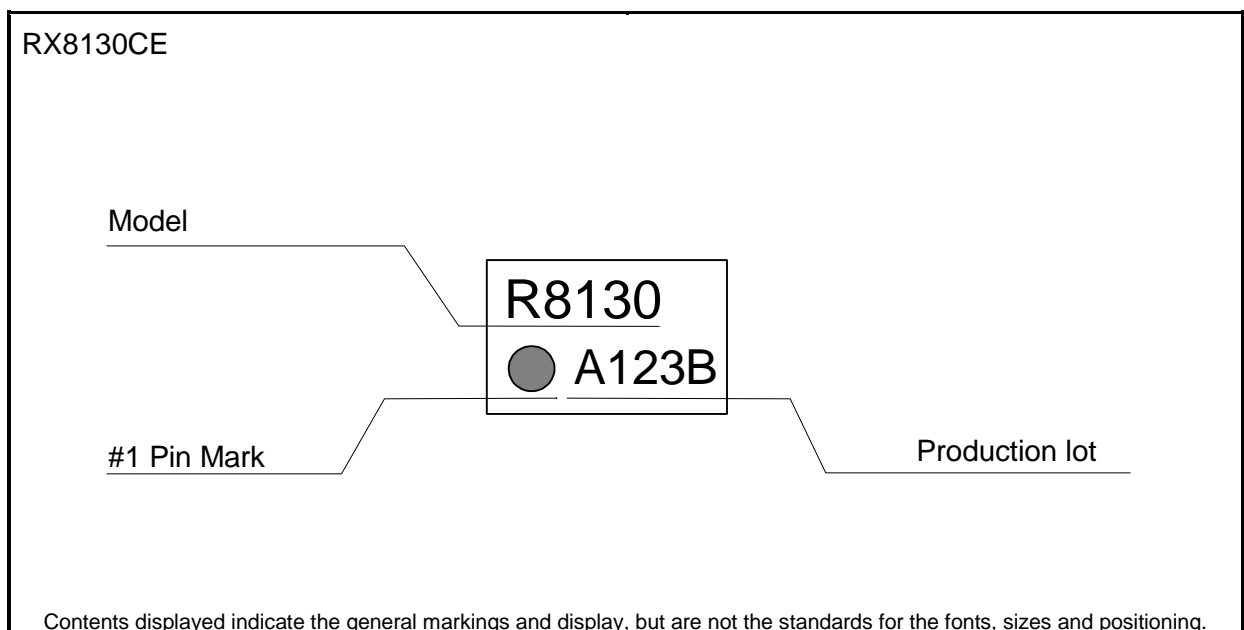


Figure 8 Marking Layout

6. Absolute Maximum Ratings

Table 2 Absolute Maximum Rating

Item	Symbol	Condition	Rating	Unit
Supply voltage	V _{DD}	–	–0.3 ~ +6.5	V
Internal voltage	V _{OUT}	–	–0.3 ~ +6.5	V
Backup supply voltage	V _{BAT}	–	–0.3 ~ +6.5	V
Interface supply voltage	V _{IO}	–	–0.3 ~ +6.5	V
Input voltage 1	V _{IN1}	SCL, SDA	–0.3 ~ +6.5	V
Output voltage 1	V _{OUT1}	/RST, /IRQ, SDA	–0.3 ~ +6.5	V
Output voltage 2	V _{OUT2}	FOUT	–0.3 ~ V _{IO} +0.3	V
		When stored separately, without packaging	–55 ~ +125	°C

7. Recommended Operating Conditions

Table 3 Recommended Operation Condition

Unless otherwise specified, GND = 0 V, Ta = –40 °C to +85 °C

Item	Symbol	Condition	Min.	Typ.	Max.	Unit
Operating supply voltage	V _{DD}	Normal operation mode (V _{DD})	1.25	3.0	5.5	V
Interface supply voltage	V _{IO}	INIEN = 0	1.6	3.0	5.5	V
		INIEN = 1	–V _{DET1}	3.0	5.5	V
Clock supply voltage	V _{CLK}	Backup operation mode (V _{OUT})	1.1	3.0	5.5	V
Operating temperature	T _{use}	No condensation	–40	+25	+85	°C

Minimum clock supply voltage of V_{CLK} is available after initializing in V_{DD}>V_{DET1}.

8. Frequency Characteristics

Table 4 Frequency Characteristics

Unless otherwise specified, GND = 0 V, Ta = –40 °C to +85 °C

Item	Symbol	Condition	Min.	Typ.	Max.	Unit
Output frequency	f _o		32.768 (Typ.)			kHz
Frequency stability	Δf / f	Ta = +25 °C V _{DD} = 3.0 V	5 ± 23 (*1)			× 10 ^{–6}
Frequency/voltage characteristics	f / V	Ta = +25 °C V _{DD} = 1.1 V ~ 5.5 V	–2		+2	× 10 ^{–6} / V
Frequency/temperature characteristics	T _{op}	Ta = –20 °C ~ +70 °C V _{DD} = 3.0 V ; +25 °C reference	–120		+10	× 10 ^{–6}
Oscillation start time	t _{Sta}	V _{DD} = 2.75 V ~ 5.5 V Internal Crystal oscillation start		0.19	1.0	s
Aging	f _a	Ta = +25 °C, V _{BAT} = 3.0 V ; first year	–5		+5	× 10 ^{–6} / year

*1) The monthly error is equal to ±60 s Max. (excluding offset)

9. Electrical Characteristics

9.1. DC characteristics

Table 5 DC characteristics (1)Unless otherwise specified, GND = 0 V, $V_{BAT} = V_{DD} = 1.1 \text{ V} \sim 5.5 \text{ V}$, $V_{IO} = 1.6 \text{ V} \sim 5.5 \text{ V}$ Ta = -40 °C to +85 °C

Item	Symbol	Condition	Min.	Typ.	Max.	Unit
Current consumption in normal operation mode without FOUT (1)	I_{DD}	SCL = SDA = "H", FOUT = OFF, /IRQ = OFF, $V_{DD}=V_{IO} = 3.0 \text{ V}$, -40 °C ~ +85 °C CHGEN = 0b or $V_{BAT} \geq V_{DET3}$		1500	1600	nA
Current consumption in normal operation with FOUT (2)	I_{32k}	SCL = SDA = "H", FOUT = 32.768 kHz, /IRQ = OFF, $V_{DD}=V_{IO} = 3.0 \text{ V}$, -40 °C ~ +85 °C FOUT pin CL = 15 pF CHGEN = 0b or $V_{BAT} \geq V_{DET3}$		3.5	4.0	μA
Current consumption in backup mode(3)	I_{BAT}	SCL = SDA = "L", $V_{BAT} = 3.0 \text{ V}$, $V_{DD}=V_{IO} = 0.0 \text{ V}$, - 40 °C ~ +85 °C		300	500	nA
Detector Threshold Voltage1 (rising edge of V_{DD})	+ V_{DET11}	2.75 V setting Reset-releases	2.72	2.80	2.88	V
Detector Threshold Voltage1 (falling edge of V_{DD})	- V_{DET11}	2.75 V setting, Reset output	2.67	2.75	2.83	V
Detector Threshold Voltage2 (rising edge of V_{DD})	+ V_{DET12}	2.7 V setting Reset-releases	2.67	2.75	2.83	V
Detector Threshold Voltage2 (falling edge of V_{DD})	- V_{DET12}	2.7 V setting, Reset output	2.62	2.70	2.78	V
Detector Threshold Voltage3 (rising edge of V_{DD})	+ V_{DET2}	Switching voltage from V_{BAT} to V_{DD}	1.25	1.35	1.45	V
Detector Threshold Voltage3 (falling edge of V_{DD})	- V_{DET2}	Switching voltage from V_{DD} to V_{BAT}	1.20	1.30	1.40	V
Detector Threshold Voltage1 (rising edge of V_{BAT})	+ V_{DET31}	Charge stop voltage (full charge) BFVSEL=00b	2.94	3.02	3.10	V
Detector Threshold Voltage1 (falling edge of V_{BAT})	- V_{DET31}	Recharge voltage. BFVSEL=00b	2.89	2.97	3.05	V
Detector Threshold Voltage2 (rising edge of V_{BAT})	+ V_{DET30}	Charge stop voltage (full charge) BFVSEL=10b	2.84	2.92	3.00	V
Detector Threshold Voltage2 (falling edge of V_{BAT})	- V_{DET30}	Recharge voltage. BFVSEL=10b	2.79	2.87	2.95	V
Detector Threshold Voltage3 (rising edge of V_{BAT})	+ V_{DET32}	Charge stop voltage (full charge) BFVSEL=01b	3.00	3.08	3.16	V
Detector Threshold Voltage3 (falling edge of V_{BAT})	- V_{DET32}	Recharge voltage. BFVSEL=01b	2.95	3.03	3.11	V
V_{BAT} end voltage	- V_{DET4}	Low V_{BAT} detection Register flag VBLF = 1b	2.32	2.40	2.48	V
V_{DD} - V_{OUT} off-leak current	I_{SW1}	$V_{OUT}=3.0 \text{ V}$, $V_{DD}=0.0 \text{ V}$			5.0	nA
V_{BAT} - V_{OUT} off-leak current	I_{SW2}	$V_{BAT}=3.0 \text{ V}$, $V_{OUT}=0.0 \text{ V}$			5.0	nA

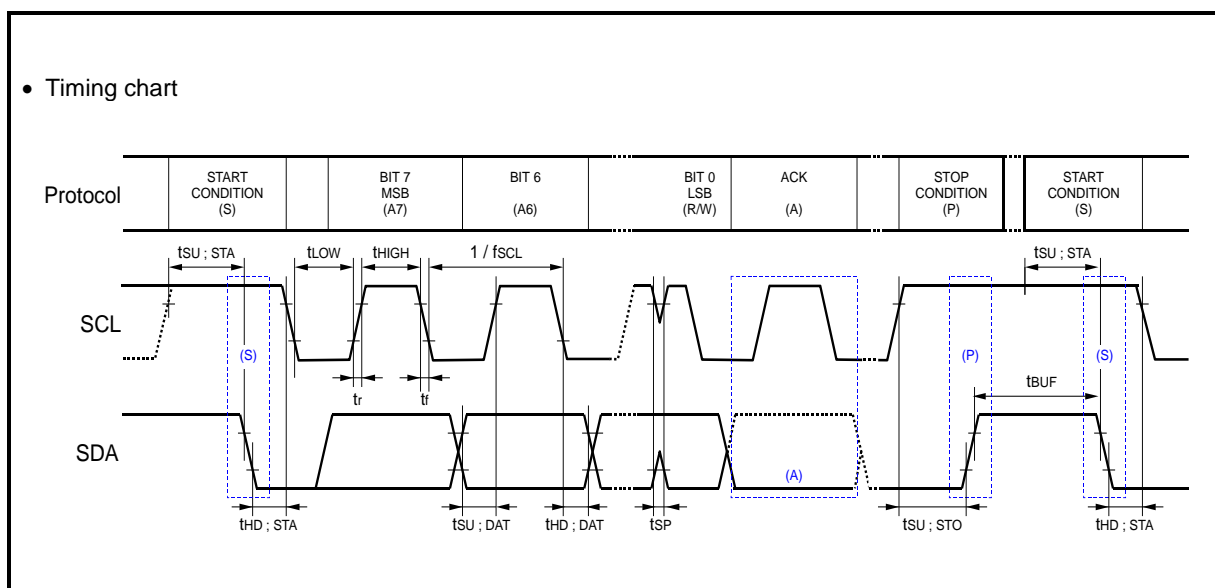
Table 6 DC characteristics(2)Unless otherwise specified GND = 0 V $V_{BAT} = V_{DD} = 1.1V \sim 5.5V$ $V_{IO} = 1.6V \sim 5.5V$ $T_a = -40\text{ }^{\circ}\text{C}$ to $+85\text{ }^{\circ}\text{C}$

Item	Symbol	Condition		Min.	Typ.	Max.	Unit
V _{OUT} output voltage 1	V _{VOUT1}	V _{DD} = 3.0 V I _{OUT} = 1 mA			V _{DD} -0.06		V
V _{OUT} output voltage 2	V _{VOUT2}	V _{BAT} = 3.0 V I _{OUT} = 0.1 mA			V _{BAT} -0.02		V
High-level input voltage	V _{IH1}	SCL, SDA		$0.8 \times V_{IO}$		5.5	V
Low-level input voltage	V _{IL}	SCL, SDA		GND – 0.3		$0.2 \times V_{IO}$	V
High-level output voltage	V _{OH}	FOUT	I _{OH} = -1 mA	V _{IO} -0.5		V _{IO}	V
Low-level output voltage	V _{OL1}	FOUT	I _{OL} = 1 mA	GND		GND+0.5	V
	V _{OL2}	/RST,/IRQ	V _{IO} = 5 V, I _{OL} = 1 mA	GND		GND+0.25	V
	V _{OL3}		V _{IO} = 3 V, I _{OL} = 1 mA	GND		GND+0.4	V
	V _{OL4}	SDA	V _{IO} ≥ 2 V, I _{OL} = 3 mA	GND		GND+0.4	V

9.2. AC characteristics

Table 7 AC characteristicsUnless otherwise specified GND = 0 V $V_{IO} = 1.6 \text{ V} \sim 5.5 \text{ V}$ $T_a = -40^\circ\text{C} \sim +85^\circ\text{C}$

Item	Symbol	Standard-Mode (fSCL=100 kHz)		Fast-Mode (fSCL=400 kHz)		Unit
		Min.	Max.	Min.	Max.	
SCL clock frequency	fSCL		100		400	kHz
Start condition setup time	tSU;STA	4.7		0.6		μs
Start condition hold time	tHD;STA	4.0		0.6		μs
Data setup time	tSU;DAT	250		100		ns
Data hold time	tHD;DAT	0		0		ns
Stop condition setup time	tSU;STO	4.0		0.6		μs
Bus idle time between start condition and stop condition	tBUF	4.7		1.3		μs
Time when SCL = "L"	tLOW	4.7		1.3		μs
Time when SCL = "H"	tHIGH	4.0		0.6		μs
Rise time for SCL and SDA	t _r		1.0		0.3	μs
Fall time for SCL and SDA	t _f		0.3		0.3	μs
Allowable spike time on bus	tSP		50		50	ns

**Figure 9 I²C-Bus Interface Timing Chart**

Warning: When accessing this device, all communication from transmitting the start condition to transmitting the stop condition after access should be completed within 0.95 seconds.
If such communication requires 0.95 seconds or longer, the I²C-Bus interface is reset by the internal bus timeout function.

When bus-time-out occur, SDA turns to Hi-Z input mode.

Note: During access to the time registers, the time counting is on hold. This means that up to 1 second can be "lost" in case of unsuccessful communication as mentioned above.

Please make sure to send I²C start condition before actual transmission of the RTCs slave address as otherwise the slave address appears to be shifted by 1 bit.

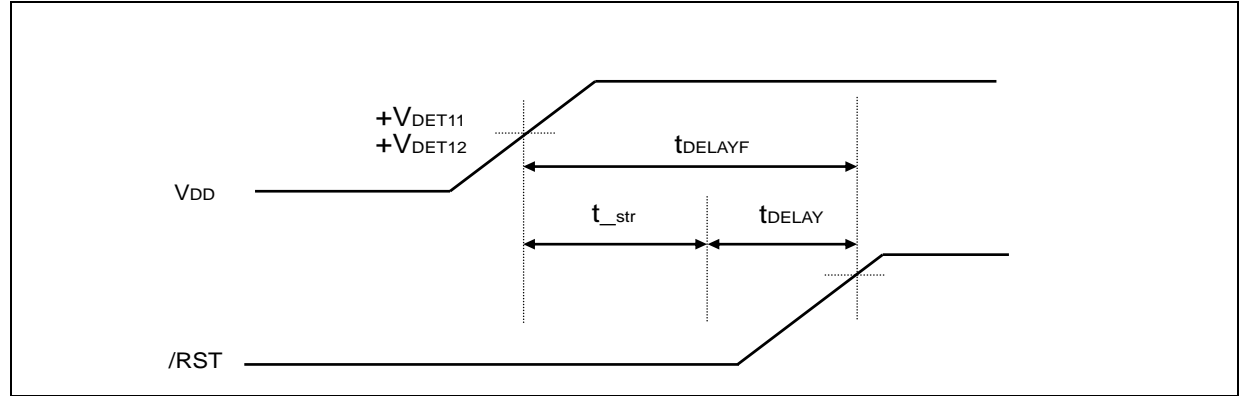
Table 8 AC characteristics (FOUT)※Unless otherwise specified GND = 0 V, $V_{IO} = 1.6 \text{ V} \sim 5.5 \text{ V}$, $T_a = -40^\circ\text{C} \sim +85^\circ\text{C}$

Item	Symbol	Condition	Min.	Typ.	Max.	Unit
FOUT symmetry	SYM	50% V_{IO} Level	40		60	%

9.2.3. AC characteristics(3)

Table 9 AC Characteristics (Reset)

Item	symbol	Min.	Typ.	Max.	unit
Reset internal delay time	t_{DELAY}		60		ms
Reset delay time (Initial power ON)	$t_{\text{DELAY_F}}$		250 ($t_{\text{str}} + t_{\text{DELAY}}$)		ms

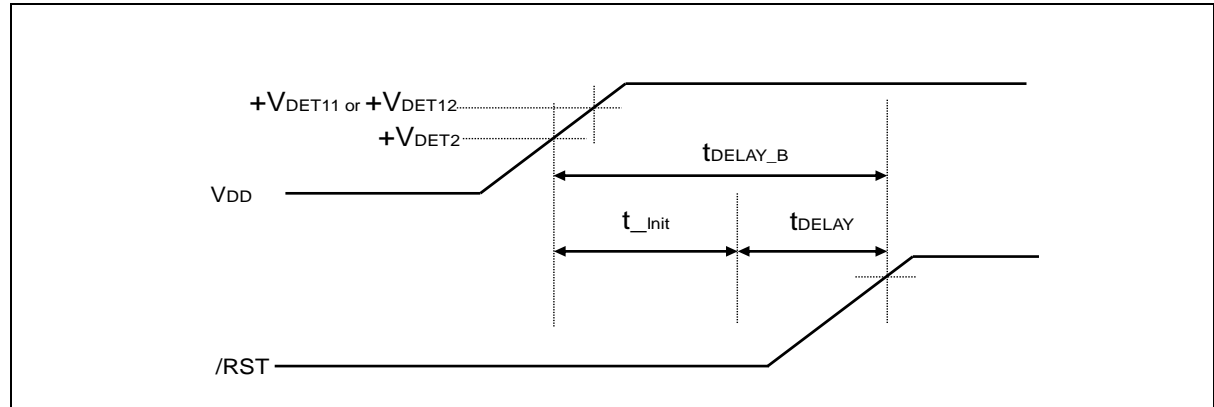


* t_{str} is oscillation startup time. See "Table4".

Figure 10 Reset signal timing chart (Power Initial Supply)

Table 10 Reset timing

Item	symbol	Min.	Typ.	Max.	unit
Voltage detection time to reset release.	t_{int}			35	ms
Reset delay time (Recovery from Backup) $t_{\text{int}} + t_{\text{DELAY}}$	$t_{\text{DELAY_B}}$	60		95	ms



t_{int} is an intermittence drive timing of a V_{DET2} detect circuit. Maximum value is 35 ms.

Figure 11 Reset signal timing chart (Backup resume)

10. Interface timing when power is turned ON / OFF

10.1. Restrictions of I²C-Bus interface in the initial power on.

The operation of the RTC register is linked to the oscillation clock of the built-in crystal unit. □

Therefore, it will not operate normally when the oscillation is stopped.

It is recommended that the initialization at the time of initial power-on is performed after the oscillation start time t_{str} characteristic.

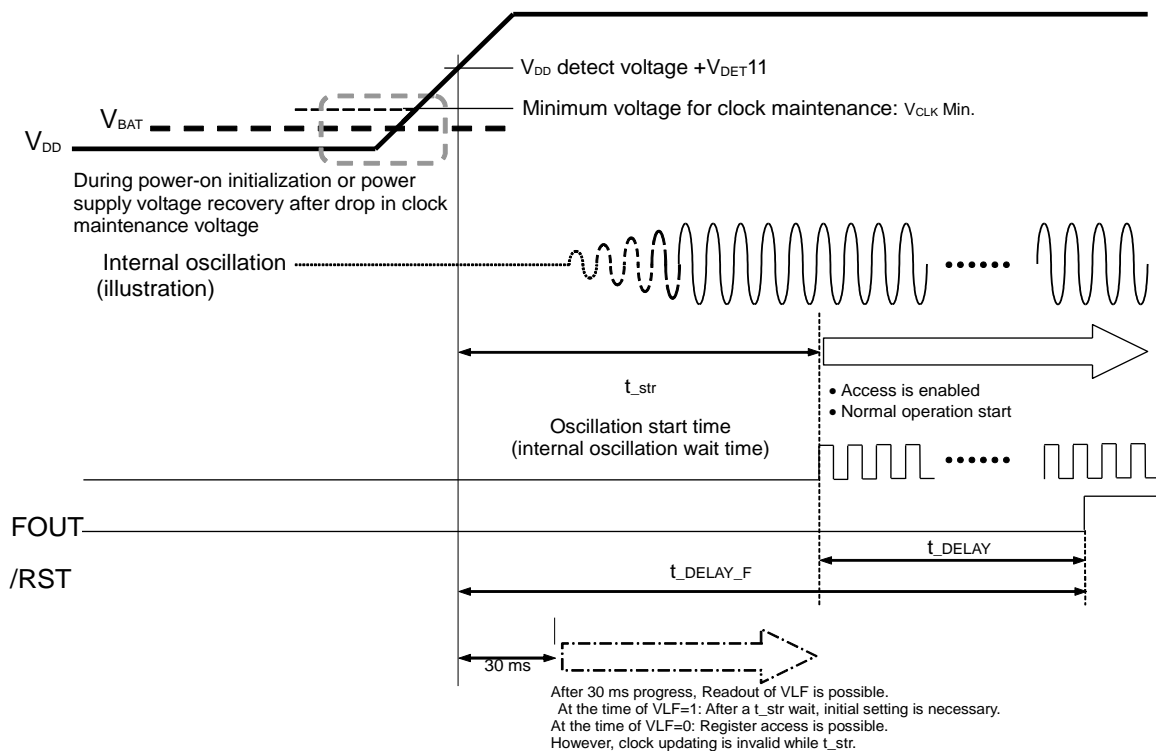


Figure 12 Power supply initial sequence

10.2. Precautions for power ON / OFF

- 1: To ensure that the power-on reset works at the initial power-on keep $V_{DD}=V_{BAT}=GND$ for 10 seconds or more before $V_{DD} = ON$.
- 2: Initial power-on t_{R1} is a necessary condition for enabling power-on reset.
If this condition is not satisfied, power-on reset may not work. As a result, the time accuracy and current consumption may not meet the specifications. Please reset by software. See [18.2 Software Reset](#).
- 3: When fluctuation of V_{DD} is out of specifications, t_F or t_{R2} , it may occur the followings, a momentary stop of crystal oscillation, a set of VLF by V_{OUT} voltage drop lower than V_{CLK} and so on.
- 4: The timing at which the I²C-Bus interface is enabled differs in when the initial power of V_{DD} is turned on and when V_{DD} is turned on from backup mode.
See the t_{CL} and t_{CU} specifications in the chart below.
- 5: These specifications don't mean a noise characteristic of a power supply of RTC.
Do not use amplitude signal output from a signal generator etc, as a power source.

10.3 V_{DD} ON / OFF when using power switching (INIEN = 1)

See "4.1. Examples of power supply connection"_Circuit EX1, 2, 3.

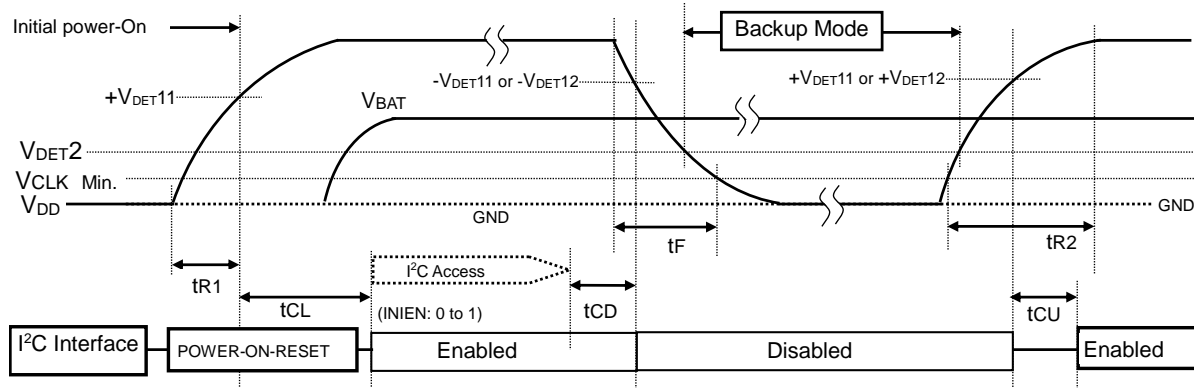


Figure 13 Power-On sequence1

10.4 V_{DD} ON / OFF when power switching is not used (INIEN = 0)

See "4.1. Examples of power supply connection"_Circuit EX4.

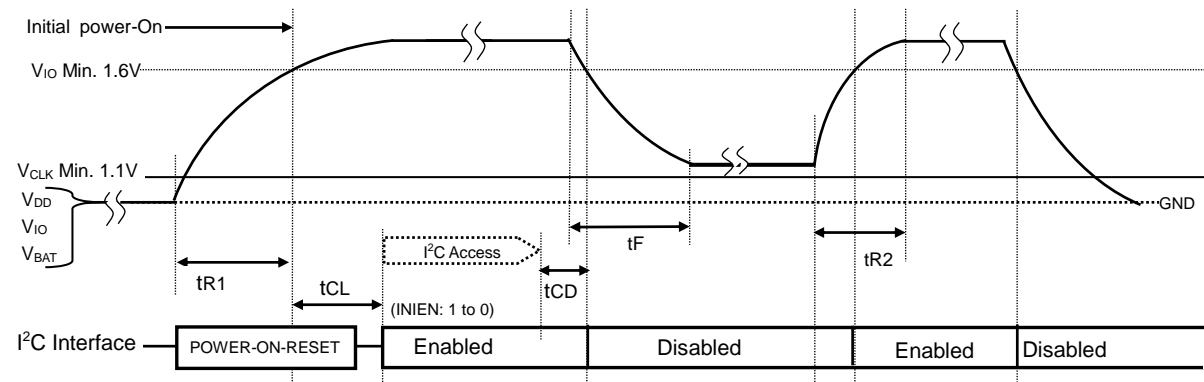


Figure 14 Power-On sequence2

Table 11 Power supply characteristics

Item	Symbol	Condition	Min.	Typ.	Max.	Unit
Power supply rise time	t _{R1}	From GND to V _{DD} = +V _{DET11}	0.1	-	10	ms / V
Access wait time	t _{CL}	V _{DD} = +V _{DET11} to Access start		-	-30	ms
Access suspended time	t _{CD}	The time from the end of I ² C access to the disable of I ² C	0	-	-	ms
Power supply fall time	t _F	From V _{DD} to V _{DD} = V _{CLK}	1	-	-	ms / V
Power supply rise time	t _{R2}	Time to restore V _{DD} to operating voltage	1	-	-	ms / V
Access wait time	t _{CU}	V _{DD} =+V _{DET1x} to Access start		-	35	ms

t_{R1}, t_{R2}, and t_F specify that there is no voltage fluctuation faster / slower than the Min / Max specifications within the specified section. The risk when specifications were not satisfied, refer to the following.

Item	Risk of fast fluctuations	Risk of slow fluctuations
t _{R1}	Power-On-Reset doesn't occur.	
t _{R2}	The FOUT waveform disappears momentarily, and clock time is momentarily delayed. A data of RTC loss. A set of VLF.	None
t _F		

V_{DD} and V_{BAT} in Figures 13 and 14 are the voltages of V_{DD} and V_{BAT} pins of RX8130CE.

Regarding access to the clock register after the initial power-on,

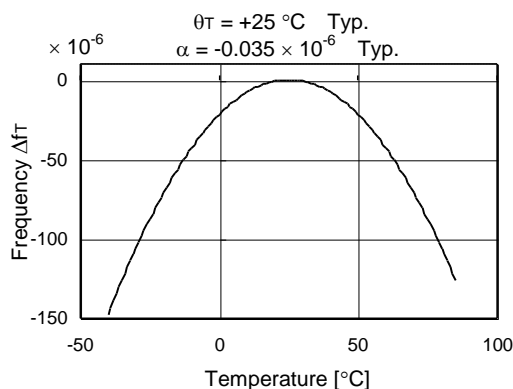
, See "10.1 restrictions of I²C interface in the initial power on". The clock from FOUT is outputted after t_{CU}.

When status of V_{DD} = V_{BAT} = GND doesn't keep more than 10seconds before initial power-on, the Power-On-Reset may not work even if the t_R / t_F specifications are satisfied.

11. Reference Information

11.1. Reference Data

(1) Example of frequency and temperature characteristics



[Finding the frequency stability]

1. Frequency and temperature characteristics can be approximated using the following equations.

$$\Delta fT = \alpha (\theta T - \theta X)^2$$

- ΔfT : Frequency deviation in any temperature
- $\alpha [1 / ^{\circ}\text{C}^2]$: Coefficient of secondary temperature
(-0.035 ± 0.005) $\times 10^{-6} / ^{\circ}\text{C}^2$
- $\theta T [^{\circ}\text{C}]$: Ultimate temperature ($+25 \pm 5\text{ }^{\circ}\text{C}$)
- $\theta X [^{\circ}\text{C}]$: Any temperature

2. To determine overall clock accuracy, add the frequency precision and voltage characteristics.

$$\Delta f/f = \Delta f/f_0 + \Delta fT + \Delta fV$$

- $\Delta f/f$: Clock accuracy (stable frequency) in any temperature and voltage.
- $\Delta f/f_0$: Frequency precision
- ΔfT : Frequency deviation in any temperature.
- ΔfV : Frequency deviation in any voltage.

3. How to find the date difference

$$\text{Date Difference} = \Delta f/f \times 86400 \text{ s}$$

* For example: $\Delta f/f = 11.574 \times 10^{-6}$ is an error of approximately 1 second / day.

Figure 15 Frequency temperature characteristics

12. Application Notes

1) Notes on handling

This module uses a C-MOS IC to realize low power consumption. Carefully note the following cautions when handling.

(1) Static electricity

While this module has built-in circuitry designed to protect it against electrostatic discharge, the chip could still be damaged by a large discharge of static electricity. Containers used for packing and transport should be constructed of conductive materials. In addition, only soldering irons, measurement circuits, and other such devices which do not leak high voltage should be used with this module, which should also be grounded when such devices are being used.

(2) Noise

If a signal with excessive external noise is applied to the power supply or input pins, the device may malfunction or "latch up." In order to ensure stable operation, connect a filter capacitor (preferably ceramic) of greater than 0.1 μF as close as possible to the power supply pins. Also, avoid placing any device that generates high level of electronic noise near this module.

(3) Voltage levels of input pins

When the voltage of out of the input voltage specifications range input into an input terminal constantly, a penetration electric current occurs. Thus, current consumption increases very much. This causes Latch-up, and there is the case that, as a result, a built-in IC is destroyed. Please use an input terminal according to input voltage specifications. Furthermore, please input the V_{IO} or GND most recent voltage as much as possible.

(4) Handling of unused pins

Disposal of unused input terminals. When an input terminal is open state, it causes increase of a consumption electric current and the behavior that are instability. Please fix an unused input terminal to the voltage that is near to V_{IO} or GND.

2) Notes on packaging

(1) Soldering heat resistance.

If the temperature within the package exceeds +260 $^{\circ}\text{C}$, the characteristics of the crystal oscillator will be degraded and it may be damaged. The reflow conditions within our reflow profile is recommended. Therefore, always check the mounting temperature and time before mounting this device. Also, check again if the mounting conditions are later changed.

(2) Mounting equipment

While this module can be used with general-purpose mounting equipment, the internal crystal oscillator may be damaged in some circumstances, depending on the equipment and conditions. Therefore, be sure to check this. In addition, if the mounting conditions are later changed, the same check should be performed again.

(3) Ultrasonic cleaning

Depending on the usage conditions, there is a possibility that the crystal oscillator will be damaged by resonance during ultrasonic cleaning. Since the conditions under which ultrasonic cleaning is carried out (the type of cleaner, power level, time, state of the inside of the cleaning vessel, etc.) vary widely, this device is not warranted against damage during ultrasonic cleaning.

(4) Mounting orientation

This device can be damaged if it is mounted in the wrong orientation. Always confirm the orientation of the device before mounting.

(5) Leakage between pins

Leakage between pins may occur if the power is turned on while the device has condensation or dirt on it. Make sure the device is dry and clean before supplying power to it.

(6) Installation of charged battery.

When a charged backup battery is installed by soldering, battery connection terminal of this device should connect to GND, beforehand.

13. Overview of Functions and Registers

Note:

The initialization of the register is necessary about the unused function.

13.1. Overview of Functions

1) Clock functions

This function is used to set and read out second, minute, hour, day, month, year (to the last two digits), and date data.

Any (two-digit) year that is a multiple of 4 is treated as a leap year and calculated automatically as such until the year 2099.

At the start of a I²C communication, the time and clock counting stops (which causes loss of time), and clock starts automatically again at the end of the I²C communication.

2) Wakeup Timer Interrupt function

The wakeup timer interrupt function generates an interrupt event periodically at any wakeup set between 244.14 μ s and 65535 hours.

When an interrupt event is generated, the /IRQ pin goes to low level and "1" is set to the TF bit to report that an event has occurred.

3) Long-Timer function

It is able to use wakeup timer interrupt function as Long-Timer or usage counter.

This function measures the operation time on the main power supply and the operation time on the backup power supply and can automatically sum them up.

4) Alarm interrupt function

The alarm interrupt function generates interrupt events for alarm settings such as date, day, hour, and minute settings. When an interrupt event occurs, the AF bit value is set to "1" and the /IRQ pin goes to low level to indicate that an event has occurred.

5) Time Update Interrupt Function

The time update interrupt function generates interrupt in one-second or one-minute intervals which are synchronized to the update of the second or minute time register of the RTC. When an interrupt event is generated, the /IRQ pin goes to low level and "1" is set to the UF bit to report that an event has occurred.

6) Frequency stop detection function

This flag bit indicates the retained status of clock operations or internal data. Its value changes from "0" to "1" when data loss might have occurred due to a low supply voltage.

7) Clock output function

A clock with the same frequency (32.768 kHz) as the built-in crystal resonator can be output from the FOUT pin. Output could also be 1 Hz, or 1024 Hz.

8) User RAM

RAM register is read/write accessible for any data.

9) Digital offset function

The clock precision can be increased by adding a time offset.

13.2. Register Table

13.2.1. Register Table

Table 12 Register Table

Address h	Function	bit 7	bit 6	bit 5	bit 4	bit 3	bit 2	bit 1	bit 0
10	SEC	0	40	20	10	8	4	2	1
11	MIN	0	40	20	10	8	4	2	1
12	HOUR	0	0	20	10	8	4	2	1
13	WEEK	0	6	5	4	3	2	1	0
14	DAY	0	0	20	10	8	4	2	1
15	MONTH	0	0	0	10	8	4	2	1
16	YEAR	80	40	20	10	8	4	2	1
17	MIN Alarm	AE	40	20	10	8	4	2	1
18	HOUR Alarm	AE	•	20	10	8	4	2	1
19	WEEK Alarm	AE	6	5	4	3	2	1	0
	DAY Alarm		•	20	10	8	4	2	1
1A	Timer Counter 0	128	64	32	16	8	4	2	1
1B	Timer Counter 1	32768	16384	8192	4096	2048	1024	512	256
1C	Extension Register	FSEL1	FSEL0	USEL	TE	WADA	TSEL2	TSEL1	TSEL0
1D	Flag Register	VBLF	0	UF	TF	AF	RSF	VLF	VBFF
1E	Control Register0	TEST	STOP	UIE	TIE	AIE	TSTP	TBKON	TBKE
1F	Control Register1	SMP TSEL1	SMP TSEL0	CHG EN	INIEN	0	RS VSEL	BF VSEL1	BF VSEL0

Address h	Function	bit 7	bit 6	bit 5	bit 4	bit 3	bit 2	bit 1	bit 0
20 23	RAM	User Register 32 bits (4-word x 8 bit)							

Address h	Function	bit 7	bit 6	bit 5	bit 4	bit 3	bit 2	bit 1	bit 0
30	Digital offset	DTE	L7	L6	L5	L4	L3	L2	L1
31	Extension Register1	-	-	-	-	-	-	-	VBLFE

After the initial power-up (from 0 V) or in case the VLF bit returns "1", make sure to initialize all registers, before using the RTC.

Be sure to avoid entering incorrect date and time data, as clock operations are not guaranteed when the data or time data is incorrect.

The TEST bit is used by the manufacturer for testing. Be sure to set "0" for this bit when writing. * Be sure to write "0" by initializing before using the clock module. Afterward, be sure to set "0" when writing "0" means that writing is invalid and the read value is always 0.

Any bit marked with "•" is a RAM bit that can be used to read or write any data.

User Register is a free register which can be used as user RAM.

The above table shows only the user registers. Due to functional reasons, RTC has different registers not mentioned above table which are programmed by the manufacturer. Please make sure to only access above mentioned user registers.

"-" bit is TEST bit. As initialization "0" should be set and be kept "0".

13.2.2. Register initial value and Read/Write operation Table

After power-on-reset, registers bits of RTC are configured automatically as below.
The value will be the same even after Software Reset is executed.

【 X: Undefined in 0 or 1. usually it keeps data of before Power-On-Reset.】
 【 0: Reset state 】
 【 1: Set state 】

Table 13 Register initial value, Read/Write

Address h	Function	bit 7	bit 6	bit 5	bit 4	bit 3	bit 2	bit 1	bit 0
10	SEC	0	X	X	X	X	X	X	X
11	MIN	0	X	X	X	X	X	X	X
12	HOUR	0	0	X	X	X	X	X	X
13	WEEK	0	X	X	X	X	X	X	X
14	DAY	0	0	X	X	X	X	X	X
15	MONTH	0	0	0	X	X	X	X	X
16	YEAR	X	X	X	X	X	X	X	X
17	MIN Alarm	X	X	X	X	X	X	X	X
18	HOUR Alarm	X	X	X	X	X	X	X	X
19	WEEK Alarm	X	X	X	X	X	X	X	X
	DAY Alarm		X	X	X	X	X	X	X
1A	Timer Counter 0	X	X	X	X	X	X	X	X
1B	Timer Counter 1	X	X	X	X	X	X	X	X
1C	Extension Register	0	0	0	0	0	1	0	0
1D	Flag Register	0	0	0	0	0	1	1	0
1E	Control Register0	0	0	0	0	0	0	0	0
1F	Control Register1	0	0	0	0	0	0	0	0

Address h	Function	bit 7	bit 6	bit 5	bit 4	bit 3	bit 2	bit 1	bit 0
20-23	RAM	X	X	X	X	X	X	X	X

Address h	Function	bit 7	bit 6	bit 5	bit 4	bit 3	bit 2	bit 1	bit 0
30	Digital offset	0	0	0	0	0	0	0	0
31	Extension Register1	0	0	0	0	0	0	0	0

13.3. Description of registers

13.3.1. Clock and calendar registers (0h ~ 16h)

This is counter registers from a second to a year.
See [\[14.1 Clock calendar explanation\]](#) for details.

13.3.2. RAM registers (20h ~ 23h)

This RAM register is read/write accessible for any data in the range from 00 h to FF h.

13.3.3. Alarm registers (17h ~ 19h)

The alarm interrupt function is used, along with the AE, AF, and WADA bits, to set alarms for specified date, day, hour, and minute values. See [\[14.3. Alarm Interrupt Function\]](#) for the details.

13.3.4. Timer setting and Timer counter register for wakeup timer (1Ah ~ 1Eh)

This register is used to set the default (preset) value for the counter.
To use the wakeup timer interrupt function, TE, TF, TIE, TSEL2, TSEL1, TSEL0, TBKON, TBKE bits are set and used. When the wakeup timer interrupt function is not being used, the wakeup timer control register can be used as a RAM register. In such cases, stop the wakeup timer function by writing "0" to the TE and TIE bits. See [\[14.2. Wakeup Timer Interrupt Function\]](#) for the details.

13.3.5. Function-related register 1 (1Ch ~ 1Eh)

1) FSEL1, FSEL0 bit

A combination of the FSEL1 and FSEL0 bits are used to select the frequency to be output.
The choice is possible by a combining FSEL-bits and CE/FOE-pin, select the frequency of clock output or inhibit the clock output. See [\[14.6. FOUT Function\]](#) for the details.

2) USEL, UF, UIE bit

This bit is used to specify either "second update" or "minute update" as the update generation timing of the time update interrupt function.
See [\[14.4. Update interrupt function\]](#) for the details.

3) TE, TF, TIE, TSEL2, TSEL1, TSEL0, TSTP, TBKON, TBKE bit

These bits are used to control operation of the wakeup timer interrupt function.

4) WADA, AF, AIE bit

These bits are used to control operation of the alarm interrupt function.

5) TEST_bit

These bits are the manufacturer's test bit. Always leave this bit value as "0" ..

6) VLF bit

This flag bit indicates the retained status of clock operations or internal data. Its value changes from "0" to "1" when data loss occurs, such as due to a supply voltage drop.

See [\[14.5. Frequency stop detection function\]](#) for the details.

7) STOP bit

This bit is to stop a timekeeping operation. In the case of "STOP bit = 1":

- 1) All the update of timekeeping and the calendar operation stops.
With it, an update interrupt event does not occur at an alarm interrupt and the time.
- 2) The part of the wakeup timer interrupt function stops.
A count stops the source clock setting of the timer in case of "64 Hz, 1 Hz, 1min, 1h".
- 3) Note 3: The effect of STOP bit to FOUT functions.
When STOP = "1", 32.768 kHz and 1024 Hz output is possible. But 1 Hz output is disabled.
- 4) Switchover function cannot work in order that the V_{DD} voltage drop detection stops even if a main power supply falls.

8) RSF bit

This flag bit holds the result of detecting the reset voltage.

13.3.6. Function-related register 2 (1Fh)

1) SMPTSEL1, SMPTSEL0 bit

Operation time setting of a voltage detector circuit for each power supply pin.

See [\[15.1. Description of Battery Backup switchover function\]](#) for the details.

2) CHGEN bit

Setting of backup battery charge control (ON/OFF).

3) INIEN bit

Setting of a power switchover function (ON/OFF).

4) RSVSEL bit

Setting of voltage detection level of a VDD pin.

5) BFVSEL1, BFVSEL0 bit

Setting of the full charge detection voltage of a backup battery.

13.3.7. Digital offset register (30h)

1) DTE bit

Setting of a Digital offset function (ON/OFF).

See [\[17. Digital offset function\]](#) for the details.

2) L7 ~ L1 bit

Setting of a Digital offset value.

14. Functions

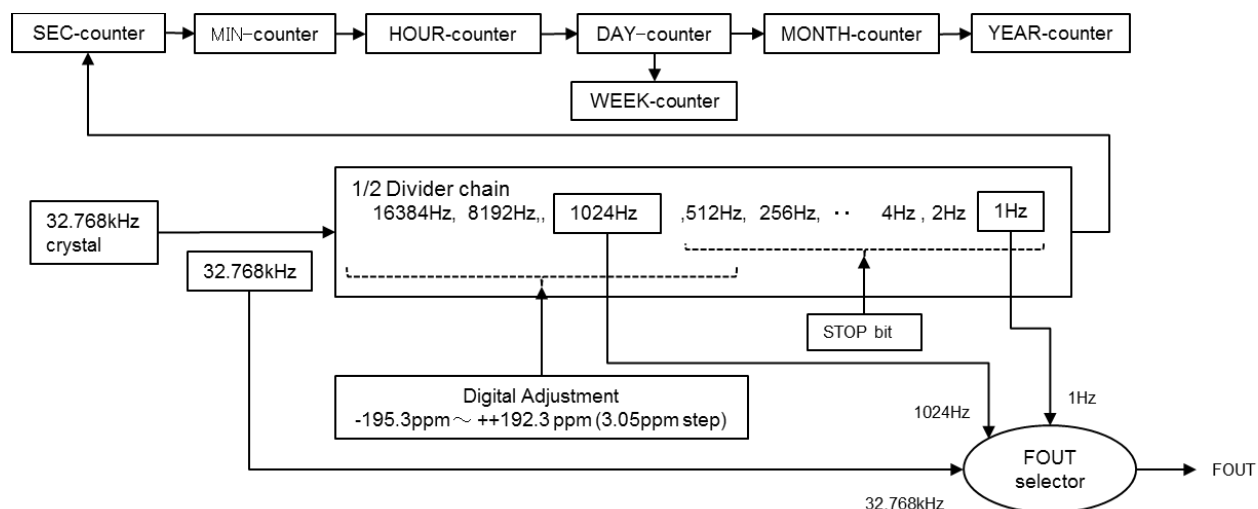


Figure 16 Basic (32.768 kHz oscillation, counter, FOUT) Function

14.1. Clock calendar explanation

At the time of a communication start, the Clock & Calendar data are fixed (hold the carry operation), and it is automatically revised at the time of the communication end. Therefore, it recommends that the access to a clock calendar has continuous access by the auto increment function.

Table 14 Time, calendar setting example (Sun, 29-Feb-88 17:39:45 (leap year))

Address h	Function	bit 7	bit 6	bit 5	bit 4	bit 3	bit 2	bit 1	bit 0
10	SEC	0	1	0	0	0	1	0	1
11	MIN	0	0	1	1	1	0	0	1
12	HOUR	0	0	0	1	0	1	1	1
13	WEEK	0	0	0	0	0	0	0	1
14	DAY	0	0	1	0	1	0	0	1
15	MONTH	0	0	0	0	0	0	1	0
16	YEAR	1	0	0	0	1	0	0	0

* Note with caution that writing non-existent time data may interfere with normal operation of the clock counter.

14.1.1. Clock counter

1) [SEC] [MIN] register

These registers are 60-base BCD counters. These registers are incremented at the timing when carry is generated from a lower register. At the timing when the lower register changes from 59 to 00, carry is generated to the higher register and thus incremented.

When writing is performed to [SEC] register, Internal-count-down-chain less than one second (512 Hz ~ 1 Hz) is cleared to 0.

2) [HOUR] register

This register is a 24-base BCD counter (24-hour format). These registers are incremented at the timing when carry is generated from a lower register.

14.1.2. Week counter

The day (of the week) is indicated by 7 bits, bit 0 to bit 6.

The day data values are counted as: Day 01h → Day 02h → Day 04h → Day 08h → Day 10h → Day 20h → Day 40h → Day 01h → Day 02h, etc.

It is incremented when carry is generated from the HOUR register. This register does not generate carry to a higher register. Since this register is not connected with the YEAR, MONTH and DAY registers, it needs to be set again with the matching day of the week if any of the YEAR, MONTH or DAY registers have been changed.

Table 15 Setting example of the week register value.

Day	bit 7	bit 6	bit 5	bit 4	bit 3	bit 2	bit 1	bit 0	Data h
Sunday	0	0	0	0	0	0	0	1	01 h
Monday	0	0	0	0	0	0	1	0	02 h
Tuesday	0	0	0	0	0	1	0	0	04 h
Wednesday	0	0	0	0	1	0	0	0	08 h
Thursday	0	0	0	1	0	0	0	0	10 h
Friday	0	0	1	0	0	0	0	0	20 h
Saturday	0	1	0	0	0	0	0	0	40 h

* Do not set "1" to more than one day at the same time.

14.1.3. Calendar counter

1) [DAY], [MONTH] register

The DAY register is a variable (between 28-base and 31-base) BCD counter that is influenced by the month and the leap year. The MONTH register is a 12-base BCD counter triggered by carryover of the day register.

		Jan.	Feb.	Mar	Apr.	May	Jun e	July	Aug.	Sep.	Oct.	Nov.	Dec.
Days	Common year	31	28	31	30	31	30	31	31	30	31	30	31
	Leap year		29										

2) YEAR] register

This register is a BCD counter for years 00 to 99.

The leap year is automatically determined and influences the DAY register.

This RTC processes following years as leap years: 00,04,08,12,,, 96.

User software correction is needed in the years 2100,2200,2300 as they are common years.

< Definition of leap years>

- Leap year : year divisible by 4 , year divisible by 400
Ex. 2000,2004,2008,2012,,, 2096,2400,2800,,,
- Common year: year indivisible by 4, year divisible by 100
Ex. 2001,2002,2003,2005,,, 2099,2100,2200,2300,2500,,

14.2. Wakeup Timer Interrupt Function

The wakeup timer interrupt function generates an interrupt event periodically at any wakeup set between 244.14 μ s and 65535 hours. This function can stop at one time and is available as an accumulative timer. After the interrupt occurs, the /IRQ status is automatically cleared.

14.2.1. Related registers for function of wakeup timer interrupt function

Address h	Function	bit 7	bit 6	bit 5	bit 4	bit 3	bit 2	bit 1	bit 0
1A	Timer Counter 0	128	64	32	16	8	4	2	1
1B	Timer Counter 1	32768	16384	8192	4096	2048	1024	512	256
1C	Extension Register	FSEL1	FSEL0	USEL	TE	WADA	TSEL2	TSEL1	TSEL0
1D	Flag Register	VBLF	0	UF	TF	AF	RSF	VLF	VBFF
1E	Control Register0	TEST	STOP	UIE	TIE	AIE	TSTP	TBKON	TBKE

- * Before entering operation settings, we recommend first clearing the TE bit to "0".
- * When the wakeup timer function is not being used, the wakeup Timer Counter0,1 register can be used as a RAM register. In such cases, stop the wakeup timer function by writing "0" to the TE and TIE bits.

1) Down counter for wakeup timer (Timer Counter 1, 0)

This register is used to set the default (preset) value for the counter. Any count value from 1 (0001 h) to 65535 (FFFFh) can be set.

Be sure to write "0" to the TE bit before writing the preset value.

- * When TE=0, read out data of timer counter is default (Preset) value. And when TE=1, read out data of timer counter is just counting value. But, when access to timer counter data, counting value is not held. Therefore, for example, perform twice read access to obtain right data, and a way to adopt the case that two data accorded is necessary.

2) TSEL2, TSEL1, TSEL0 bit

The combination of these three bits is used to set the countdown period (source clock) for this function.

Table 16 Countdown period (source clock) selection

TSEL2 (bit 2)	TSEL1 (bit 1)	TSEL0 (bit 0)	Source clock		Auto reset time tRTN (min)
0	0	0	4096 Hz	/Once per 244.14 μ s	122 μ s
0	0	1	64 Hz	/Once per 15.625 ms	7.57 ms
0	1	0	1 Hz	/Once per second	7.57 ms
0	1	1	1/60 Hz	/Once per minute	7.57 ms
1	0	0	1/3600 Hz	/Once per hour	7.57 ms

- *1) The /IRQ pin's auto reset time (tRTN) varies as shown above according to the source clock setting.
- *2) The first countdown shortens than a source clock.
When selected 4,096 Hz / 64 Hz / 1Hz as a source clock, one period of error occurs at the maximum.
When selected 1/60 Hz / 1/3600 Hz as a source clock, 1 Hz of error occurs at the maximum.

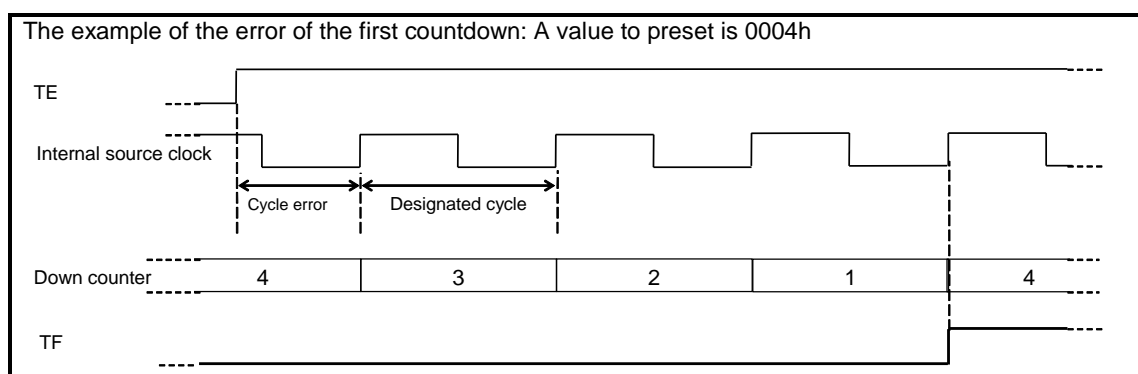
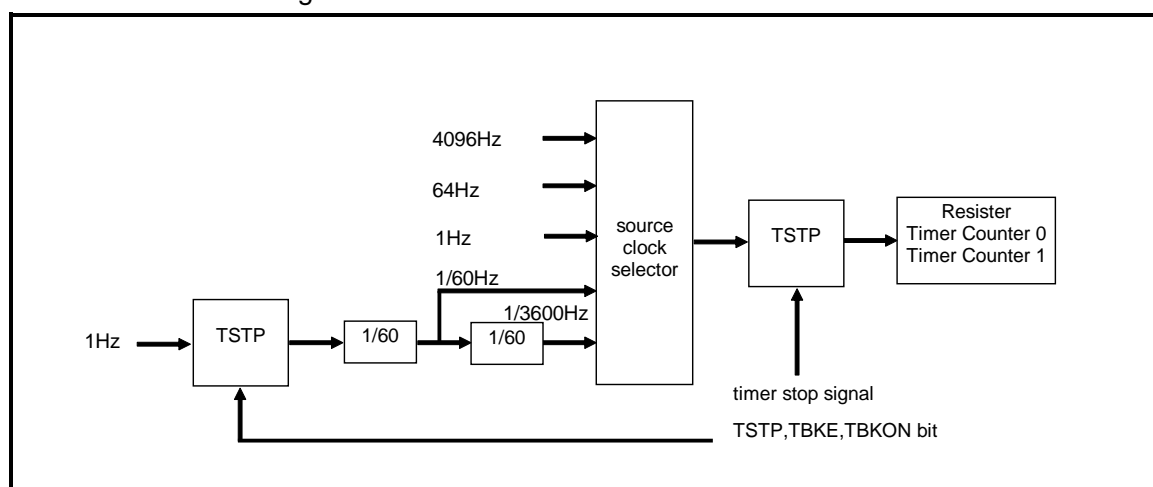


Figure 17 Wakeup timer initial sequence

Inside counter block diagram



Note: The resolution of the count value depends on the source clock

Figure 18 Wakeup timer block diagram

3) TE bit (Timer Enable)

When TE bit is "0", the default (preset) can be checked by reading this register.

Table 17 Wakeup timer control

TE	Data	Description
Write	0	Stops wakeup timer interrupt function. * Clearing this bit to zero does not enable the /IRQ low output status to be cleared (to Hi-z).
	1	Starts wakeup timer interrupt function. * The countdown that starts when the TE bit value changes from "0" to "1" always begins from the preset value.

4) TF bit (Timer Flag)

This is a flag bit that retains the result when a wakeup timer interrupt event is detected.

Table 18 Wakeup timer interrupt detection flag

TF	Data	Description
Write	0	The TF bit is cleared to zero to prepare for the next status detection * Clearing this bit to zero does not enable the /IRQ low output status to be cleared (to Hi-z).
	1	Invalid (writing a 1 will be ignored)
Read	0	–
	1	Wakeup timer interrupt events are detected. (Result is retained until this bit is cleared to zero.)

5) TIE bit (Timer Interrupt Enable)

This bit is used to control output of interrupt signals from the /IRQ pin when a wakeup timer interrupt event has occurred.

Table 19 Wakeup timer interrupt control

TIE	Data	Description
Write	0	1) When a wakeup timer interrupt event occurs, an interrupt signal is not generated. 2) When a wakeup timer interrupt event occurs, the interrupt signal is canceled (/IRQ status changes from low to Hi-z).
	1	When a wakeup timer interrupt event occurs, an interrupt signal is generated (/IRQ status changes from Hi-z to low).

6) TBKON, TBKE bit

This function selects the operation time with the main power supply or the operation time with the backup power supply. The count value is added.

Table 20 Wakeup timer normal mode/backup mode control

operation	TBKE	TBKON	Description
Write	0	X	This setting counts normal mode and backup mode.
	1	0	This setting counts it at time of normal mode(VDD operation)
		1	This setting counts it at time of backup mode (VBAT operation)

7) TSTP bit (Timer Stop)

This bit is used to stop wakeup timer count down.

Table 21 Wakeup timer stop control

TE	STOP	TBKE	TSTP	Description
1	0	0	0	Writing a "0" to this bit cancels stop status (restarts timer count down). *The reopening value of the countdown is a stopping value
			1	Count stops.
		1	X	Setting of TSTP value becomes invalid, and the count does not stop even if set it in TSTP="1".
	1	X	X	The count stops at the time of the setting of 64 Hz, 1 Hz, 1/60 Hz, 1/3600 Hz.
0	X	X	X	It doesn't start counting

14.2.2. Wakeup timer start timing

Counting down of the wakeup timer value starts at the rising edge of the SCL (ACK output) signal that occurs when the TE value is changed from "0" to "1".

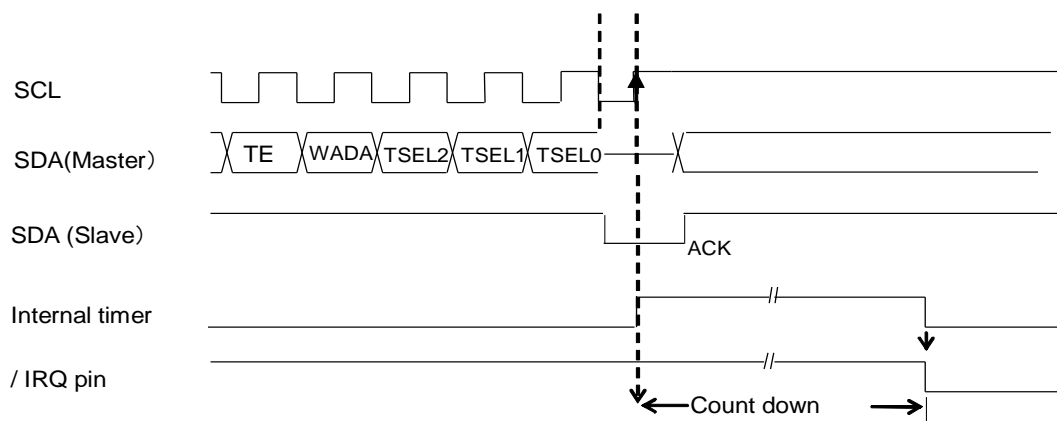


Figure 19 Wakeup timer start sequence

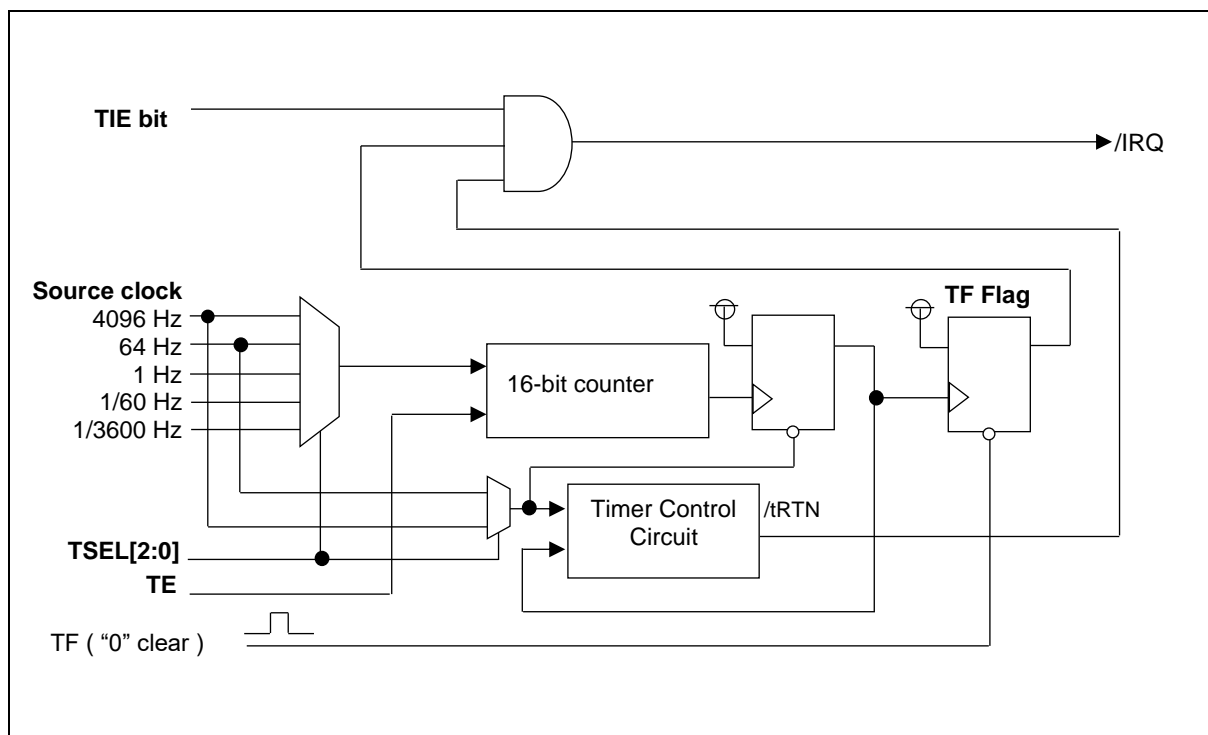
14.2.3. Wakeup timer interrupt interval (example)

The combination of the source clock settings and wakeup timer countdown setting sets interrupt interval, as shown in the following examples.

Table 22 Wakeup timer interrupt cycles

Timer Counter setting 1 ~ 65535	Source clock				
	4096 Hz TSEL2 = 0 TSEL1, 0 = 0, 0	64 Hz TSEL2 = 0 TSEL1, 0 = 0, 1	1 Hz TSEL2 = 0 TSEL1, 0 = 1, 0	1 / 60 Hz TSEL2 = 0 TSEL1, 0 = 1, 1	1 / 3600 Hz TSEL2 = 1 TSEL1, 0 = 0, 0
0	—	—	—	—	—
1	244.14 μ s	15.625 ms	1 s	1 min	1 h
:	:	:	:	:	:
410	100.10 ms	6.406 s	410 s	410 min	410 h
:	:	:	:	:	:
3840	0.9375 s	60.000 s	3840 s	3840 min	3840 h
:	:	:	:	:	:
4096	1.0000 s	64.000 s	4096 s	4096 min	4096 h
:	:	:	:	:	:
65535	15.9998 s	1023.984 s	65535 s	65535 min	65535 h

14.2.4. Diagram of wakeup timer interrupt function

**Figure 20 Wakeup timer inner block diagram**

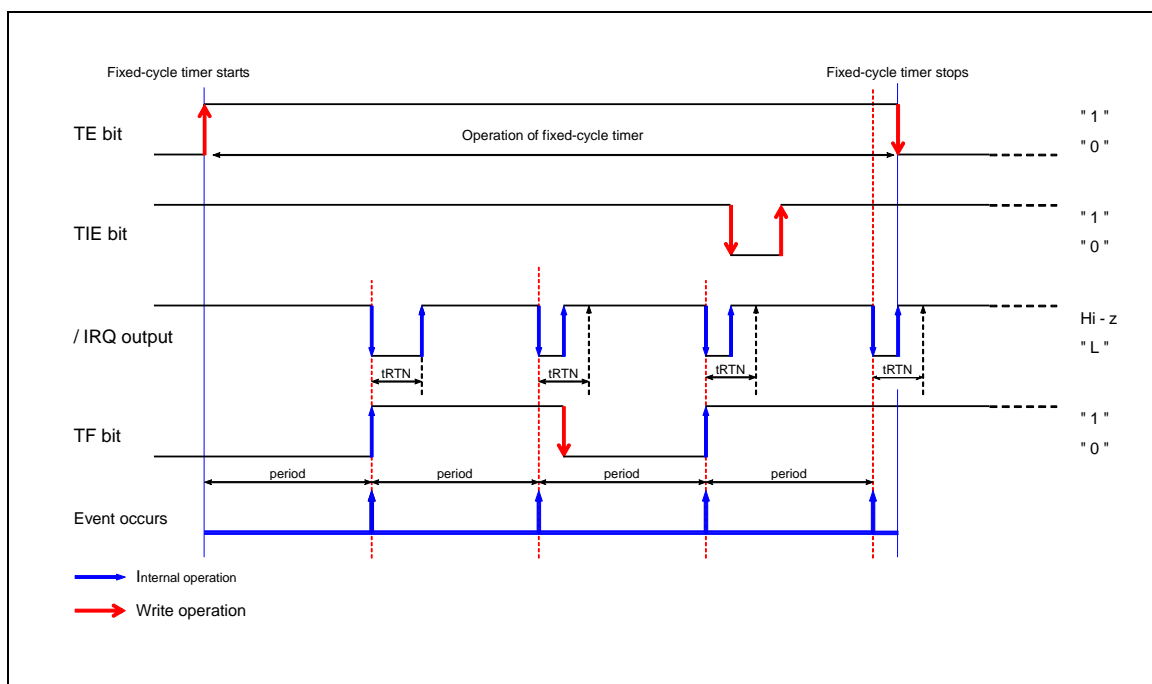


Figure 21 Wakeup timer timing chart

- (1) A time update interrupt event occurs when the internal clock's value matches either the second update time or the minute update time. The USEL bit's specification determines whether it is the second update time or the minute update time that must be matched.
- (2) When a time update interrupt event occurs, the UF bit value becomes "1".
- (3) When the UF bit value is "1" its value is retained until it is cleared to zero.
- (4) When a time update interrupt occurs, /IRQ pin output is low if UIE = "1".
* If UIE = "0" when a timer update interrupt occurs, the /IRQ pin status remains Hi-Z.
- (5) Each time an event occurs, /IRQ pin output is low only up to the tRTN time (which is fixed as min 7.57 ms for time update interrupts) after which it is automatically cleared to Hi-Z.
* /IRQ pin output goes low again when the next interrupt event occurs.
- (6) As long as /IRQ = low, the /IRQ pin status does not change, even if the UF bit value changes from "1" to "0".
- (7) When /IRQ = low, the /IRQ pin status changes from low to Hi-Z as soon as the UIE bit value changes from "1" to "0".

14.3. Alarm Interrupt Function

The alarm interrupt function generates interrupt events for alarm settings such as date, day, hour, and minute settings.

When an interrupt event occurs, the AF bit value is set to "1" and the /IRQ pin goes to low level to indicate that an event has occurred. AF bit and /IRQ output show a maximum delay of 1.46ms from the alarm event.

* /IRQ="L" output when occurs alarm interruption event is not cancelled automatically unless giving intentional cancellation and /IRQ="L" are maintained.

14.3.1. Related registers for Alarm interrupt functions.

Address h	Function	bit 7	bit 6	bit 5	bit 4	bit 3	bit 2	bit 1	bit 0
17	MIN Alarm	AE	40	20	10	8	4	2	1
18	HOUR Alarm	AE	•	20	10	8	4	2	1
19	WEEK Alarm	AE	6	5	4	3	2	1	0
	DAY Alarm		•	20	10	8	4	2	1
1C	Extension Register	FSEL1	FSEL0	USEL	TE	WADA	TSEL2	TSEL1	TSEL0
1D	Flag Register	VBFLF	0	UF	TF	AF	RSF	VLF	VBFF
1E	Control Register0	TEST	STOP	UIE	TIE	AIE	TSTP	TBKON	TBKE

* Before entering settings for operations, we recommend writing a "0" to the AIE bit to prevent hardware interrupts from occurring inadvertently while entering settings.

* When the STOP bit value is "1" alarm interrupt events do not occur.

* When the alarm interrupt function is not being used, the Alarm registers (Reg – 17h to 19h) can be used as a RAM register. In such cases, be sure to write "0" to the AIE bit.

* When the AIE bit value is "1" and the Alarm registers (Reg – 17h to 19h) is being used as a RAM register, /IRQ may be changed to low level unintentionally.

1) AE bit

The minute, hour, day and date when an alarm interrupt event will occur is set using this register and the WADA bit.

In the WEEK alarm /Day alarm register (Reg – 19h), the setting selected via the WADA bit determines whether WEEK alarm data or DAY alarm data will be set. If WEEK has been selected via the WADA bit, multiple days can be set (such as Monday, Wednesday, Friday, Saturday).

When the settings made in the alarm registers and the WADA bit match the current time, the AF bit value is changed to "1". At that time, if the AIE bit value has already been set to "1", the /IRQ pin goes low.

Note: AE-bit is low active, so in order to enable 1 interrupt every hour once the actual minutes match the alarm setting, it is necessary to set the AE of register 17h to 0 and the AE of 18h and 19h to 1.

In order to generate an alarm interrupt only once a week, all 3 AE-bits have to be set "0"

*1) The alarm function is not a HW feature but software function inside the RTC.

*2) In case "AE" bit of register 19h is set to "1", the day will be ignored, and an interrupt occurs ones the actual time matches the minutes and/or hour setting of the alarm register.

(Example) Write 80h (AE = "1") to the WEEK Alarm /DAY Alarm register (Reg - 19h):

Only the hour and minute settings are used as alarm comparison targets. The week and date settings are not used as alarm comparison targets.

As a result, alarm occurs if only the hour and minute values match the alarm data.

*3) If all three AE bit values are "1" the week/date and time settings are ignored, and an alarm interrupt event will occur once per minute.

2) WADA bit (Week Alarm / Day Alarm Select)

The alarm interrupt function uses either "Day" or "Week" as its target. The WADA bit is used to specify either WEEK or DAY as the target for alarm interrupt events.

Table 23 WEEK/DAY control

WADA	Data	Description
Write	0	Sets WEEK as target of alarm function
	1	Sets DAY as target of alarm function

3) AF bit (Alarm Flag)

When this flag bit value is already set to "0", occurrence of an alarm interrupt event changes it to "1".

When this flag bit value is "1", its value is retained until a "0" is written to it.

Table 24 Alarm Flag

AF	Data	Description
Write	0	Clearing this bit to zero enables /IRQ low output to be canceled (/IRQ remains Hi-z) when an alarm interrupt event has occurred.
	1	Invalid (writing a 1 will be ignored)!
Read	0	–
	1	Alarm interrupt events are detected. (Result is retained until this bit is cleared to zero.)

4) AIE bit (Alarm Interrupt Enable)

This bit is used to control output of interrupt signals from the /IRQ pin when an Alarm interrupt event has occurred.

Table 25 Alarm Interrupt control

AIE	Data	Description
Write	0	1) When an alarm interrupt event occurs, an interrupt signal is not generated or is canceled (/IRQ status remains Hi-z). 2) When an alarm interrupt event occurs, the interrupt signal is canceled (/IRQ status changes from low to Hi-z).
	1	When an alarm interrupt event occurs, an interrupt signal is generated (/IRQ status changes from Hi-z to low).

The AIE bit is only output control of the /IRQ terminal. It is necessary to clear an AF flag to cancel alarm.

14.3.2. Examples of alarm settings

- 1) Example of alarm settings when "Week" has been specified (and WADA bit = "0")

Table 26 WEEK alarm example

Week is specified WADA bit = "0"	Week Alarm								HOUR Alarm	MIN Alarm
	bit 7 AE	bit 6 S	bit 5 F	bit 4 T	bit 3 W	bit 2 T	bit 1 M	bit 0 S		
Monday through Friday, at 7:00 AM * Minute value is ignored	0	0	1	1	1	1	1	0	07 h	AE bit = 1
Every Saturday and Sunday, for 30 minutes each hour * Hour value is ignored	0	1	0	0	0	0	0	1	AE bit = 1	30 h
Every day, at 6:59 AM	0 1	1 X	1 X	1 X	1 X	1 X	1 X	1 X	18 h	59 h

X: Don't care

2) Example of alarm settings when "Day" has been specified (and WADA bit = "1")

Table 27 DAY alarm example

Day is specified WADA bit = "1"	Day Alarm								HOUR Alarm	IN Alarm
	bit 7	bit 6	bit 5	bit 4	bit 3	bit 2	bit 1	bit 0		
	AE	•	20	10	08	04	02	01		
First of each month, at 7:00 AM * Minute value is ignored	0	0	0	0	0	0	0	1	07 h	AE bit = 1
15 th of each month, for 30 minutes each hour * Hour value is ignored	0	0	0	1	0	1	0	1	AE bit = 1	30 h
Every day, at 6:59 PM	1	X	X	X	X	X	X	X	18 h	59 h

X: Don't care

14.3.3. Diagram of alarm interrupt function

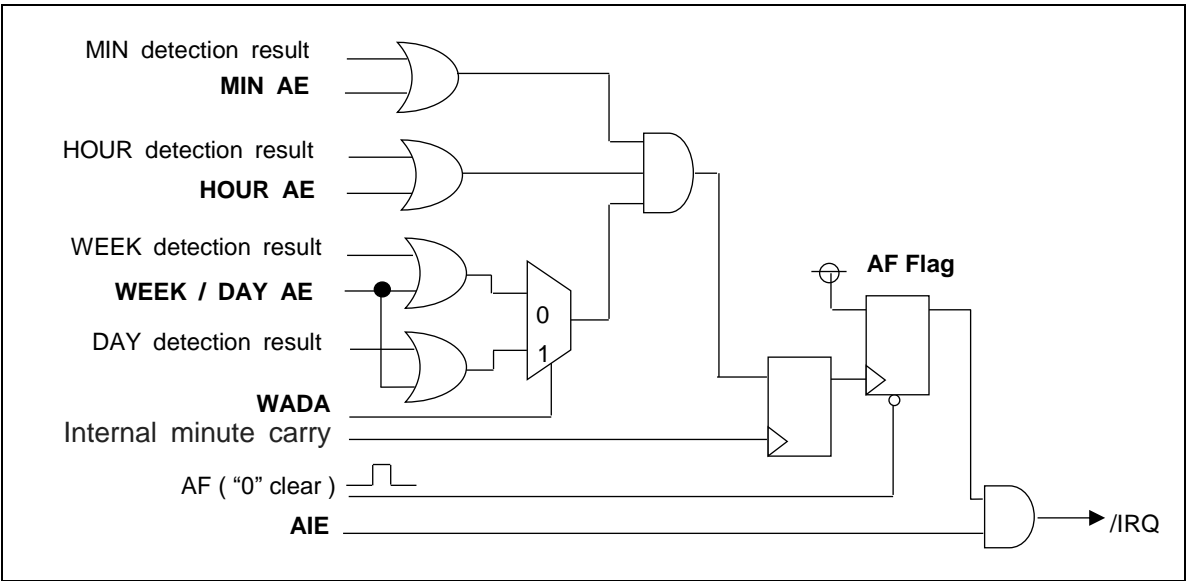


Figure 22 Alarm interrupt inner block diagram

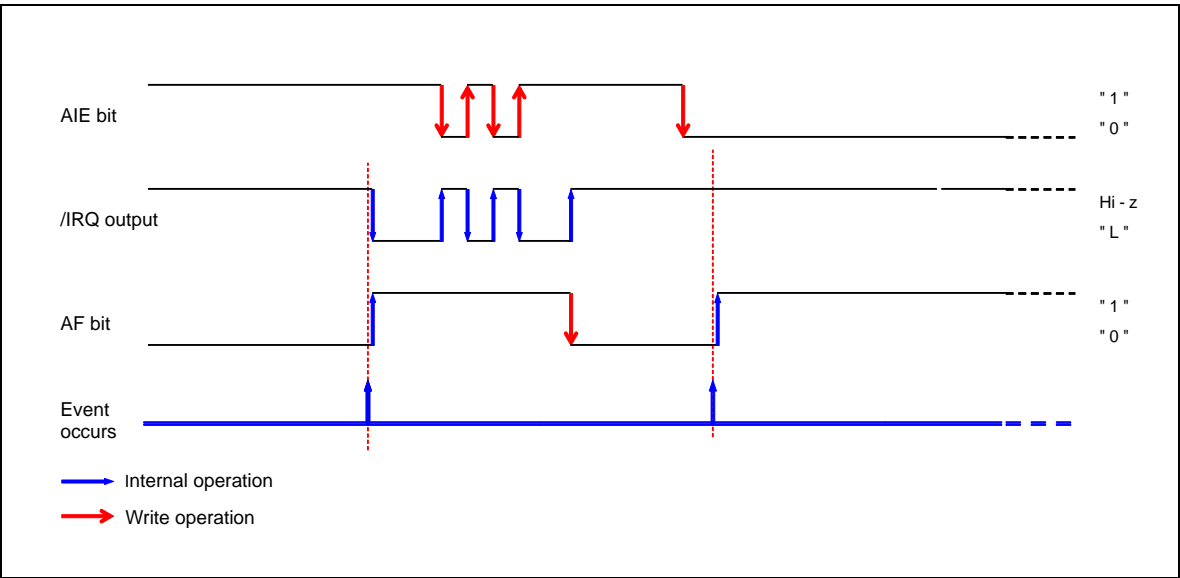


Figure 23 Alarm Interrupt time chart

14.4. Time Update Interrupt Function

The time update interrupt function generates interrupt in one-second or one-minute intervals which are synchronized to the update of the second or minute time register of the RTC. When an interrupt event is generated, this /IRQ status is automatically cleared (/IRQ status changes from low level to Hi-Z earliest 7.57ms (maximum 15.63ms) after the interrupt occurs).

14.4.1. Related registers for time update interrupt functions.

Address h	Function	bit 7	bit 6	bit 5	bit 4	bit 3	bit 2	bit 1	bit 0
1C	Extension Register	FSEL1	FSEL0	USEL	TE	WADA	TSEL2	TSEL1	TSEL0
1D	Flag Register	VBLF	0	UF	TF	AF	RSF	VLF	VBFF
1E	Control Register0	TEST	STOP	UIE	TIE	AIE	TSTP	TBKON	TBKE

- * Before entering settings for operations, we recommend writing a "0" to the UIE bit to prevent hardware interrupts from occurring inadvertently while entering settings.
- * When the STOP bit value is "1" time update interrupt events do not occur.
- * Although the time update interrupt function cannot be fully stopped, if "0" is written to the UIE bit, the time update interrupt function can be prevented from changing the /IRQ pin status to low.

1) USEL bit (Update Interrupt Select)

This bit is used to select "second" update or "minute" update as the timing for generation of time update interrupt events.

Table 28 Second/Minute selection

USEL	Data	Description
Write	0	Selects "second update" (once per second) as the timing for generation of interrupt events
	1	Selects "minute update" (once per minute) as the timing for generation of interrupt events

2) UF bit (Update Flag) This flag bit value changes from "0" to "1" when a time update interrupt event occurs.

Table 29 Time update Flag

UF	Data	Description
Write	0	Clearing this bit to zero enables /IRQ low output to be canceled (/IRQ remains Hi-Z) when a time update interrupt event has occurred.
	1	Invalid (writing a 1 will be ignored)
Read	0	–
	1	Time update interrupt events are detected. (The result is retained until this bit is cleared to zero.)

3) UIE bit (Update Interrupt Enable)

This bit selects whether to generate an interrupt signal or to not generate it.

Table 30 Time update interrupt control

UIE	Data	Description
Write / Read	0	1) Does not generate an interrupt signal when a time update interrupt event occurs (/IRQ remains Hi-Z) 2) Cancels interrupt signal triggered by time update interrupt event (/IRQ changes from low to Hi-Z). * Even when the UIE bit value is "0" another interrupt event may change the /IRQ status to low (or may hold /IRQ = "L").
	1	When a time update interrupt event occurs, an interrupt signal is generated (/IRQ status changes from Hi-Z to low). * When a time update interrupt event occurs, low-level output from the /IRQ pin occurs only when the UIE bit value is "1". Earliest 7.57 ms after the interrupt occurs, the /IRQ status is automatically cleared (/IRQ status changes from low to Hi-Z).

14.4.2. Time update interrupt function diagram

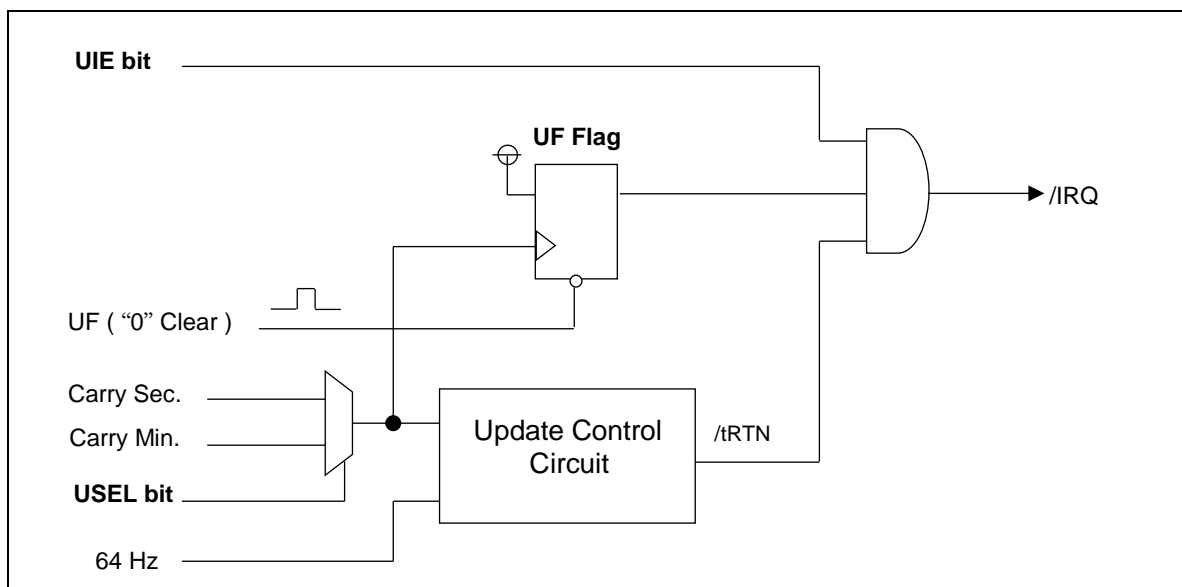


Figure 24 Time update inner block diagram

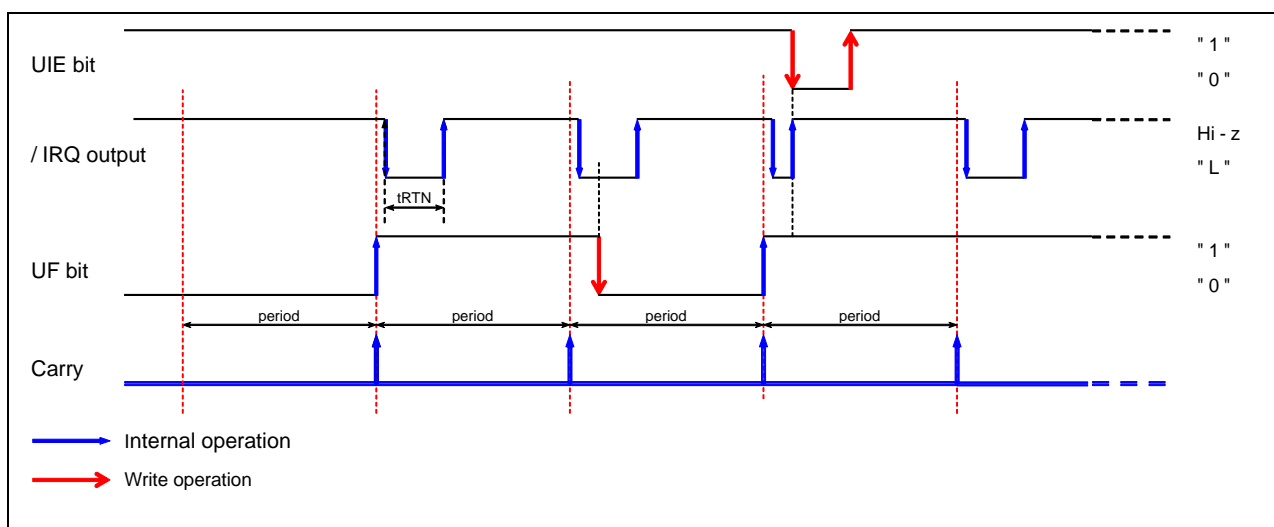


Figure 25 Time update time chart

14.5. Oscillation stop detection function

This flag bit indicates the retained status of clock oscillation stop. Its value changes from "0" to "1" when data loss might have occurred due to clock oscillation stop, power on resetting. Once this flag bit's value is "1", its value is retained until a "0" is written to it.

During the initial power-on (from 0 V) and/or if the value of the VLF bit is "1", be sure to initialize all registers before using them.

14.5.1. Related registers for Oscillation stop and Voltage low detect function.

Address h	Function	bit 7	bit 6	bit 5	bit 4	bit 3	bit 2	bit 1	bit 0
1D	Flag Register	VBLF	0	UF	TF	AF	RSF	VLF	VBFF

1) VLF bit

Table 31 Oscillation stop detection flag

VLF	Data	Description
Write	0	The VLF is cleared to 0 and waiting for next low voltage detection.
	1	Invalid (writing 1 will be ignored)
Read	0	Oscillation status is normal, RTC register data are valid.
	1	Oscillation stop is detected, RTC register data are invalid. Should be initialized of all register data. VLF is maintained till it is cleared by zero.

14.6. FOUT function

The clock signal can be output via the FOUT pin. Output is stopped upon detection of the voltage drop below V_{DET1} In this case pin output becomes Hi-z.

14.6.1. FOUT control register.

Address h	Function	bit 7	bit 6	bit 5	bit 4	bit 3	bit 2	bit 1	bit 0
1C	Extension Register	FSEL1	FSEL0	USEL	TE	WADA	TSEL2	TSEL1	TSEL0

14.6.2. FOUT function Table.

3) FSEL1,FSEL0 bit

Table 32 FOUT Frequency selection

FSEL1	FSEL0	output
0	0	32.768 kHz Output
0	1	1024 Hz Output
1	0	1 Hz Output
1	1	OFF

At the time of the initial power-on, "0" is set to FSEL1, FSEL0 by Power-On-Reset..

Note: The effect of STOP bit to FOUT functions.

When STOP = "1", 32.768 kHz and 1024 Hz output is possible.

But 1 Hz output is disabled.

15 Battery backup switchover function

15.1. Description of Battery backup switchover function

This function consists of a supply voltage detector "VDET" which detects if the supply voltage of the main power source connected to "VDD" drops below a threshold (V_{DET2}), and three MOS switches (SW1, SW2A and SW2B) located between the main power-source pin "VDD" and the backup power supply pin "VBAT". (Figure 26 Battery backup switchover block diagram)

The MOS-switches SW1, SW2A and SW2B are activated according to the result of the supply-voltage detection of V_{DET2} and the RTC changes the operating modes between normal mode (RTC power supply = V_{DD}) or backup mode (RTC power supply = V_{BAT}).

The RTCs backup function is built in a way to prevent reverse current flow from V_{BAT} to V_{DD} . While in backup-mode, the I2C-bus and FOUT function are switched off and related terminals switched to Hi-Z.

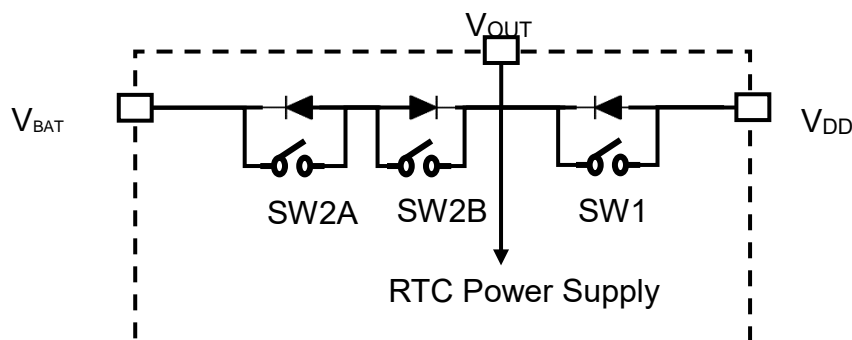


Figure 26 Battery backup switchover block diagram

15.2 Reference characteristics of switching elements.

Table 33 Reference characteristics of switching elements.

Item	Value	Condition
Limit of current.	40 mA Max.	SW1 = SW2A = SW2B = ON, +25 °C
Diode Vf	0.60 V / 1 mA Typ. 0.85 V / 10 mA Typ.	$V_{DD} = 3.0 \text{ V}$, +25 °C
Diode IR	5 nA Max.	$V_R = 5.5 \text{ V}$, -40 °C ~ +85 °C

Use a secondary battery, EDLC, etc, with the charge current of 40 mA or less.

15.3 Reference characteristics of the charge current

Graph show an electric current characteristic (all SW1, SW2B, SW2A, resistance characteristic of ON) that can charge a second battery.

It is reference value in 25 °C.

When V_{DD} voltage is high, The charge current increase.

And when little voltage differences of V_{DD} and V_{BAT} , charge current is decreasing.

A vertical axis shows charge current I_{chg} and a horizontal axis shows voltage difference V_{def} between V_{DD} and V_{BAT} .

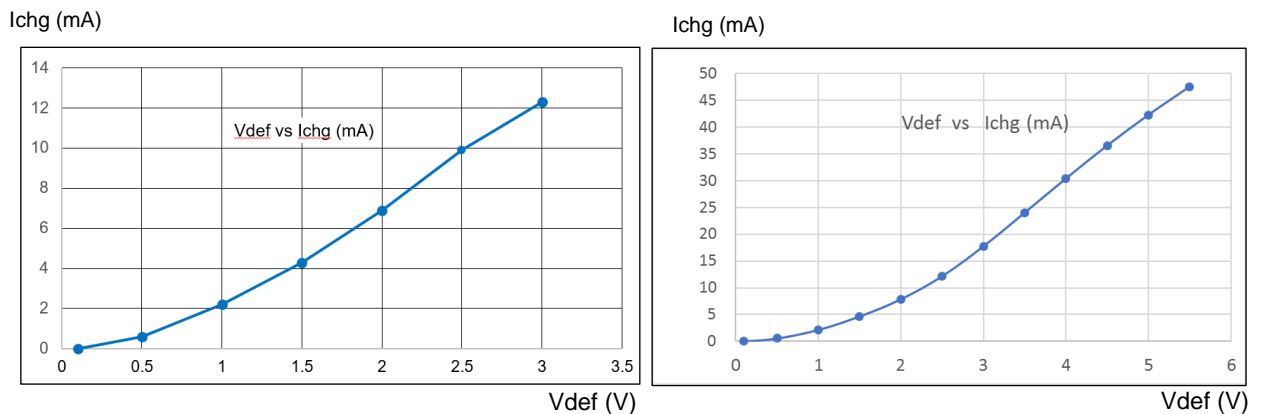


Figure 27 V_{BAT} charge current characteristics $V_{DD} = 3.0\text{ V}, 5.5\text{ V}$

15.4 Re-Chargeable battery Voltage Current features

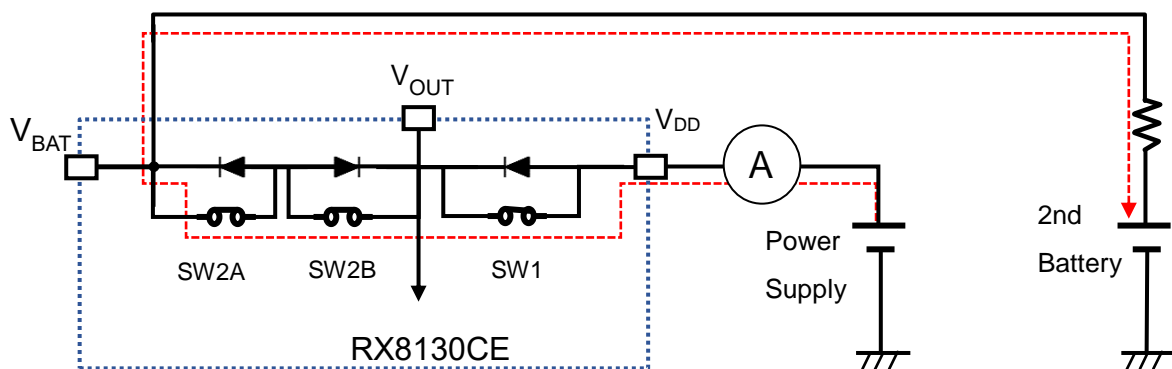


Figure 28 Re-chargeable battery connection

15.5. Related register of Battery backup switchover function

Address h	Function	bit 7	bit 6	bit 5	bit 4	bit 3	bit 2	bit 1	bit 0
1D	Flag Register	VBLF	0	UF	TF	AF	RSF	VLF	VBFF
1F	Control Register1	SMP TSEL1	SMP TSEL0	CHG EN	INIEN	0	RS VSEL	BF VSEL1	BF VSEL0

1) CHGEN bit

This bit has to be set to allow charging of a Re-chargeable battery connected to V_{BAT} from V_{DD} pin.

Table 34 CHGEN bit

CHGEN	Data	Description
Write / Read	0	For non-re-chargeable battery use (default setting). During V_{DD} drive SW2 is OFF, battery charging is not available.
	1	SW1, SW2 automatic controlled. For re-chargeable battery use

In case of re-chargeable battery use, INIEN should be set to 1 to enable SW1, SW2 automatic control.
To stop battery charging CHGEN should be reset to 0.

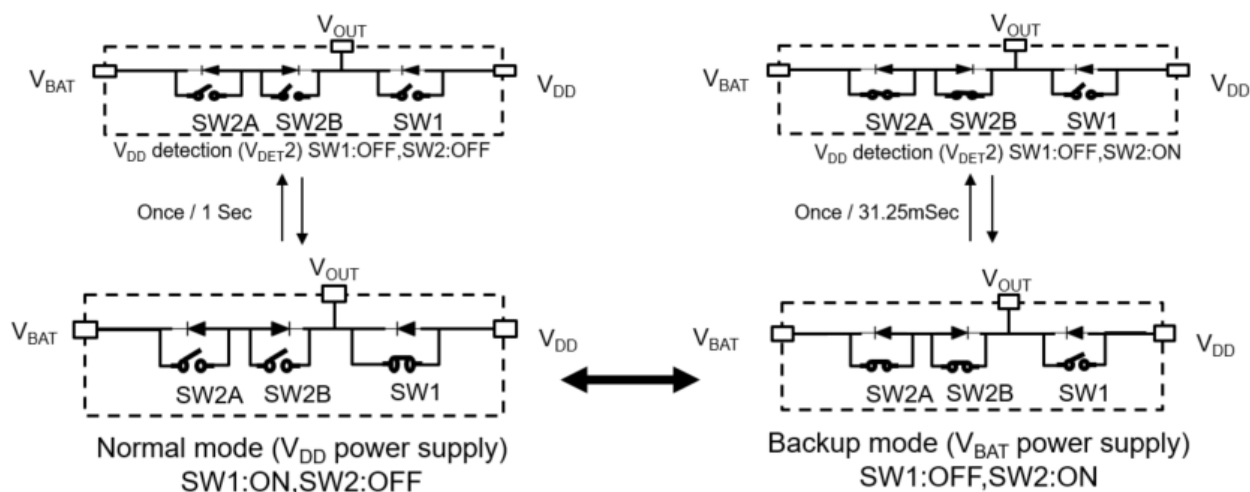
2) INIEN bit

Note1: When INIEN is used with 0, it must be set up "INIEN=1" before the setting once at least. When INIEN-bit is used with 0 from just Power-On-Reset value all the time, there is the case that INIEN=0 mode is incorrect working. For example, Power switching doesn't work. Therefore, that an INIEN bit is set to 1 in initial setting is recommended.
See "[initial setting example](#)".

Note2: when INIEN set to 1 from 0 in $V_{DD} < V_{DET1}$, I²C is disabled immediately. Therefore while $V_{DD} < V_{DET1}$, I²C can't cleared INIEN to 0.

Table 35 INIEN bit

INIEN	Data	Description
Write / Read	0	After INIEN=1, I ² C and FOUT function is available regardless of V_{DET1} detection. Power-switching is available. CHGEN-bit function is disabled. It same as CHGEN = 0. be careful not to input intermediate voltage to the I ² C interface.
	1	I ² C, FOUT function is not available while $V_{DD} < V_{DET1}$. I ² C, FOUT function is available while $V_{DD} > V_{DET1}$. CHGEN bit function is enabled.

**Figure 30 Non Re-chargeable battery SW1, SW2 control (INIEN = 1, CHGEN = 0)**

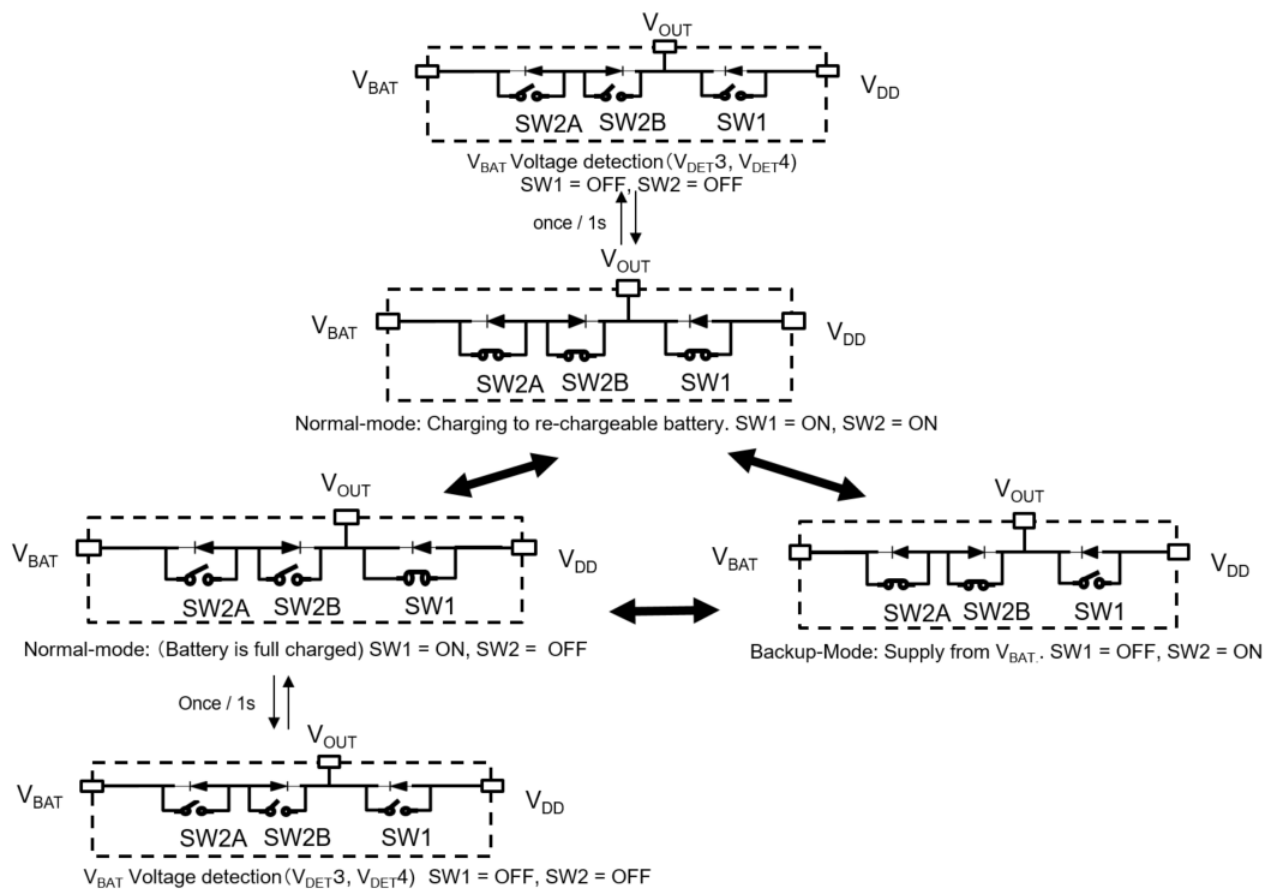


Figure 31 Re-chargeable battery SW1, SW2 control (INIEN = 1, CHGEN = 1)

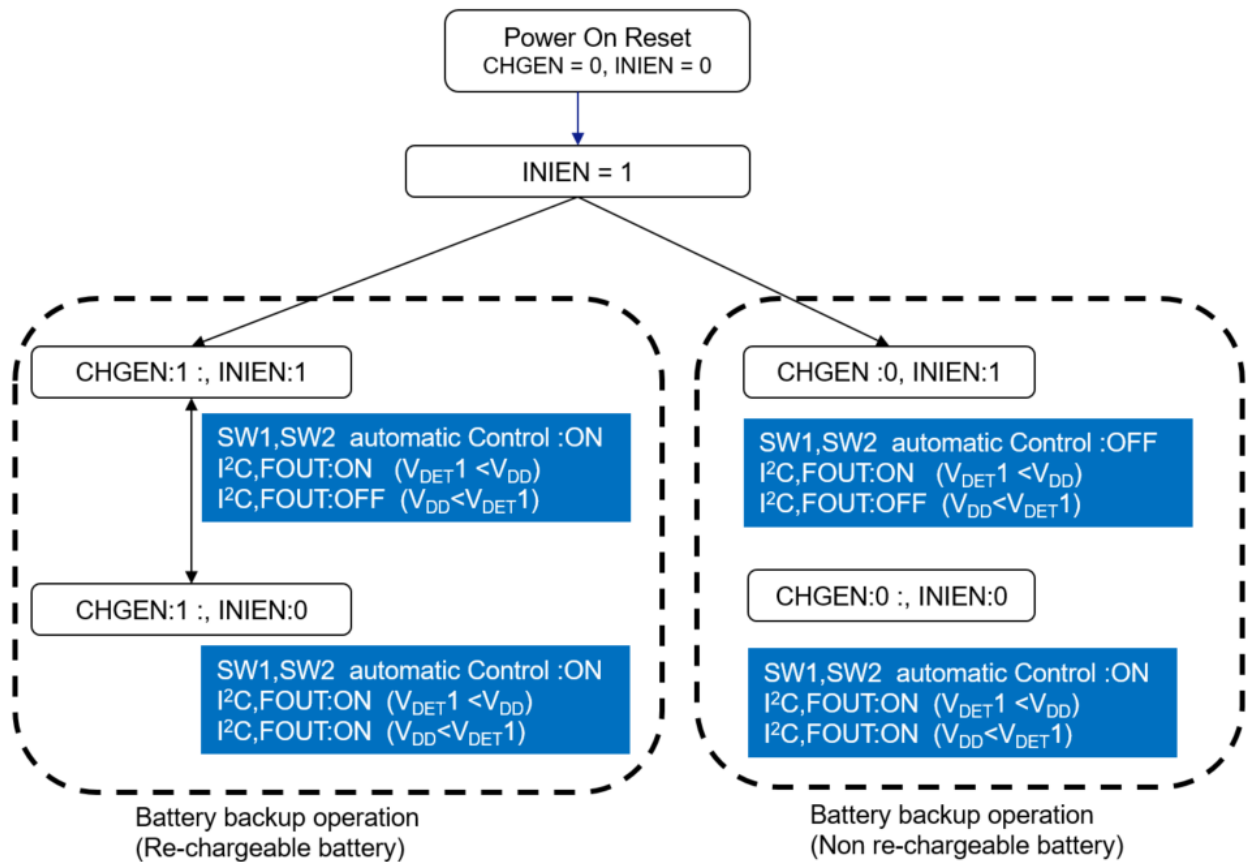


Figure 32 Battery backup (SW1, SW2 automatic control)

3) SMPTSEL1, SMPTSEL0 bit

- V_{DD} voltage detection: V_{DET1} (reset), V_{DET2} (voltage down):
 Battery backup detection (V_{DET2}) is done constantly and SW1 is opened periodically for V_{DD} measurement.
 During SW1:ON, external voltage to V_{DD} cannot be measured precisely because RTC internal voltage is leaked to V_{DD} external voltage supply circuit even external circuit is down. So periodical SW1 = OFF makes disconnection between RTC internal voltage and external voltage supply, thus V_{DD} external voltage is measured precisely. V_{DD} external voltage drop moves to backup mode.
 See [Figure 30 \$V_{DD}\$ detection \(\$V_{DET2}\$ \) timing](#).
- V_{BAT} voltage detection: V_{DET3} (V_{BAT} full charge), V_{DET4} (V_{BAT} over discharge)
 In case of normal mode, V_{BAT} voltage is precisely and periodically detected with condition (SW1 OFF, SW2 OFF). The detection period is determined by combination of SMPTSEL1, SMPTSEL0.
 See [Figure 31 for \$V_{DET3}\$, \$V_{DET4}\$ voltage detection timing](#)

(In case of CHGEN = 0, There is no charge operation SW2 = OFF)

Table 36 Voltage detection timing

Power supply mode	Normal mode (Backup battery is charging)	Normal mode (Backup battery is fully charged)	Normal mode (After return from backup $V_{DET1} > V_{DD} > V_{DET2}$)	Backup mode
Reset detection $V_{DD} < V_{DET1}$	Constantly ON	Constantly ON	Constantly ON	Constantly OFF
Power switching detection $V_{DD} < V_{DET2}$	Constantly ON	Constantly ON	Constantly ON	Once/31.25 ms
Full charge detection $V_{BAT} > V_{DET3}$	Once/1.0 s	Once/1.0 s	Once/1.0 s	Constantly OFF
Low- V_{BAT} detection $V_{DD} < V_{DET4}$	Once/1.0 s	Once/1.0 s	Once/1.0 s	Constantly OFF

* In normal mode, when operating the RTC on V_{DD} -supply, SW1 has to be opened (Off) to perform the V_{DD} voltage detection for below mentioned times

Table 37 V_{DET3} , V_{DET4} intermittent detection period

Power supply operation mode		V_{DD} operation (Backup battery is charging)	V_{DD} operation (Backup battery is fully charged)	V_{DD} operation (After return from backup $V_{DET1} > V_{DD} > V_{DET2}$)
	SMPTSEL1,0			
SW1 Off time. *	00b (default)	2 ms	2 ms	2 ms
	01b	16 ms	16 ms	2 ms
	10b	128 ms	128 ms	2 ms
	11b	256 ms	256 ms	2 ms

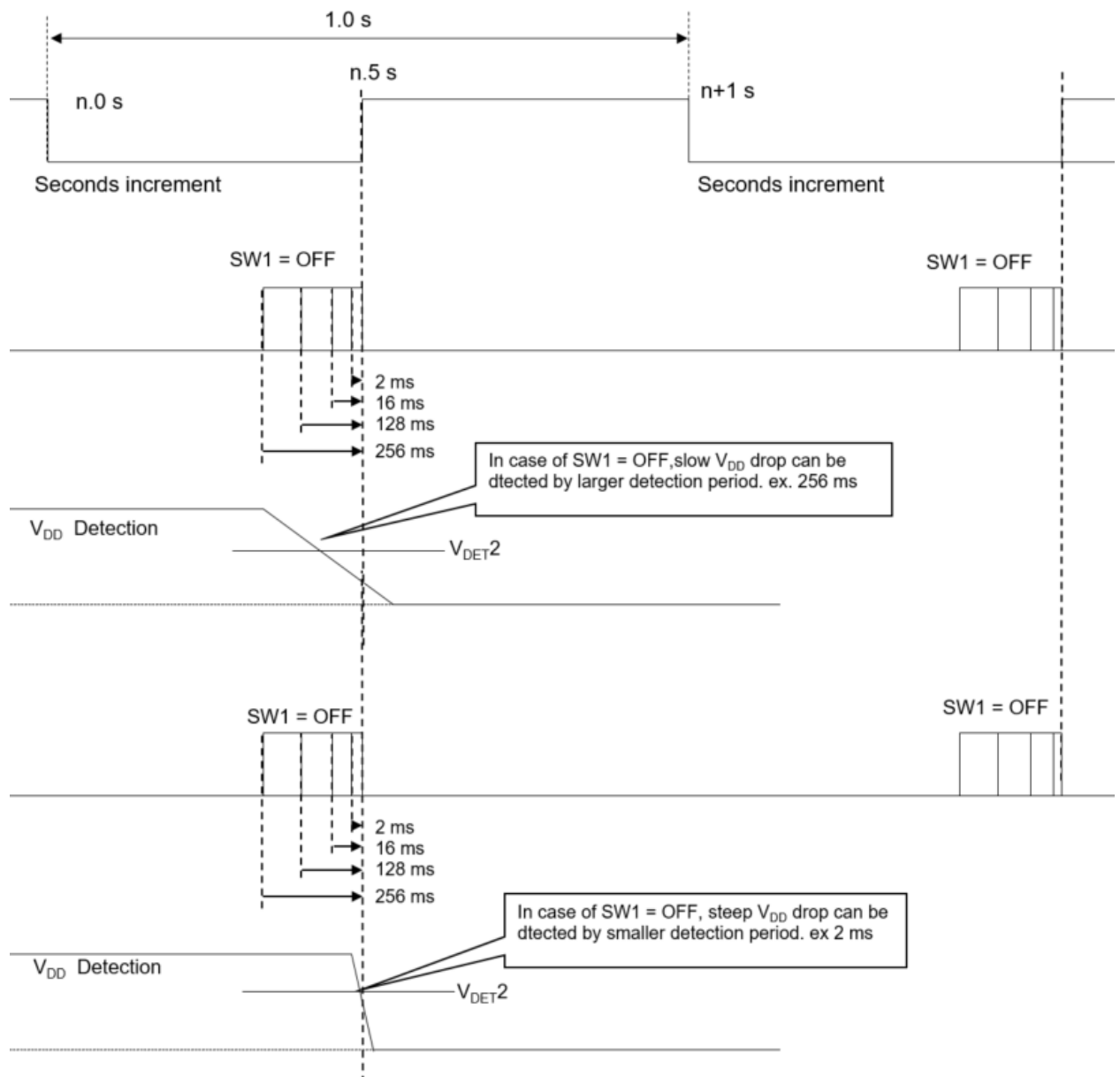


Figure 33 V_{DD} detection (V_{DET2}) timing

V_{DD} voltage drop detection (V_{DET2}) is work always, in Normal mode.

Shorter SW1:OFF times are suitable to detect fast external voltage drops on V_{DD}. On the other hand, in order to detect a slower external voltage drop on V_{DD}, a longer SW1:OFF detection time is needed. But longer SW1:OFF period increases the current consumption.

Users are requested to evaluate SW1:OFF period based on actual system configuration and characteristics.

In backup mode V_{DD} detection (V_{DET2}) is activated once every 31.25 ms.

Note: Re-chargeable battery is charged through diode during the term of SW1 = OFF. Longer this term (ex. 256 ms) makes decreasing battery charging efficiency.

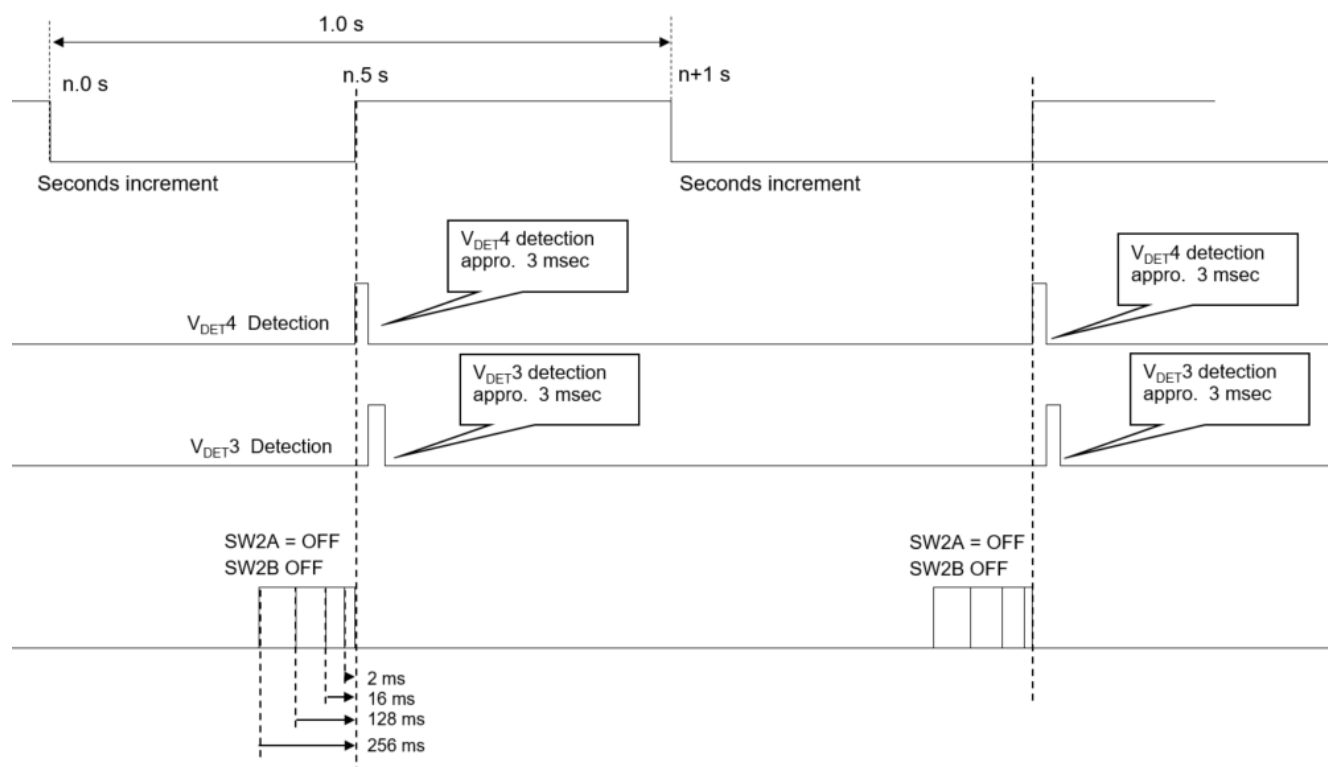


Figure 34 VDET3, VDET4 voltage detection timing) BFVSEL1, BFVSEL0 bit

15.6 Detection voltage setting

Table 38 VDET1,VDET2,VDET3,VDET4 setting

	Item	Symbol	Detect voltage Typ.	setting
VDET1	Reset /Reset-release voltage	+VDET11 / -VDET11	2.8V / 2.75V	RSVSEL = 0 (default)
		+VDET12 / -VDET12	2.7V / 2.65V	RSVSEL = 1
VDET2	Backup switchover/recover voltage	+VDET2 / -VDET2	1.35V / 1.30V	
VDET3	Full charge detection voltage	+VDET31 / -VDET31	3.02V / 2.97V	BFVSEL = 00b (default)
		+VDET30 / -VDET30	2.92V / 2.87V	BFVSEL = 01b
		+VDET32 / -VDET32	3.08V / 3.03V	BFVSEL = 10b
VDET4	V _{BAT} low-voltage detection voltage	-VDET4	2.4V	

- 4) The full-charge detection (VDET3) and low-V_{BAT} detection (VDET4) control SW2.

Table 39 BFVSEL1, BFVSEL0

BFVSEL1	BFVSEL0	Description
0	0	3.02 V (default)
0	1	3.08 V
1	0	2.92 V
1	1	OFF (Charging without limit)

5) VBFF bit

This bit indicates if the battery is fully charged (update Every 1sec)

Table 40 VBFF

VBFF	Data	Description
Read	0	Charging
	1	Full charge of V _{BAT} detected (voltage level defined by BFFVSEL-bit is reached)

This flag shows the V_{BAT} charge state.

6) VBLF bit

Low V_{BAT} detection

Table 41 VBLF

VBLF	Data	Description
Write	0	Cleared to zero to prepare for the next status detection.
	1	Invalid (writing a 1 will be ignored)
Read	0	–
	1	Low-V _{BAT} has been detected (V _{DET4})

7) VBLFE bit

Re-chargeable battery full charge detection (Every 1 s)

Table 42 VBLFE

VBLFE	Data	Description
Write	0	CHGEN:0 VBLF detection not available CHGEN:1 VBLF detection available (during normal mode re-chargeable battery charging)
	1	During V _{DD} supply VBLF detection available

To use VBLF detection, it must be set up "INIEN=1" before the setting once at least, and VBLFE bit setting. During normal mode (V_{DD} drive) V_{BAT} low voltage (Non-rechargeable, rechargeable battery) can be detected. In case of backup mode VBLF function is not available, VBLF is detected after returning to normal mode.

9): STOP bit function

When STOP=1, in backup-mode, 31.25ms period of V_{DET2} detection stops.

As a result, power supply switching becomes insufficient, and there is the possibility that a leak current occurs.

When STOP=1 and shift to backup-mode, clear the STOP bit to 0 after V_{DD}-ON immediately.

15.7. Power supply control

By setting battery backup registers (INIEN, CHGEN), the RX8130CE operates like following either in re-chargeable battery or non-re-chargeable battery operation.

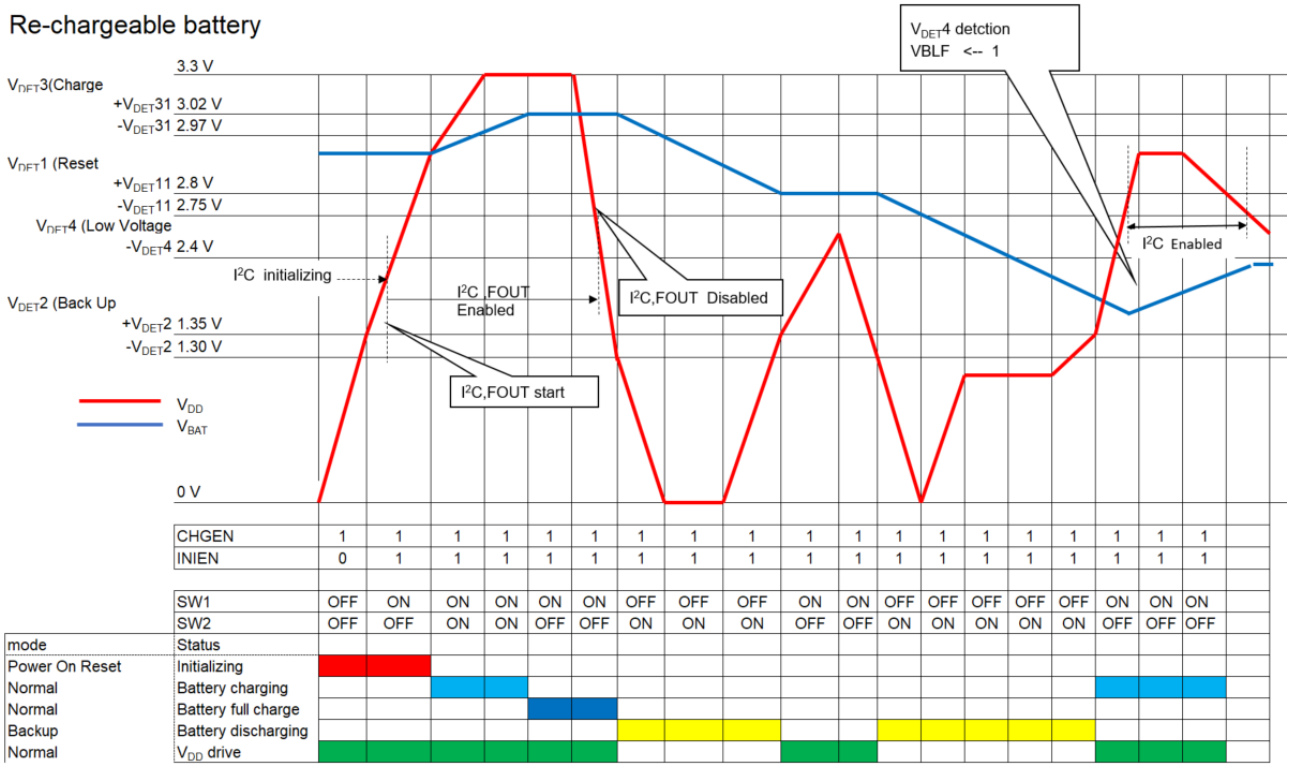


Figure 35 Re-chargeable battery operation

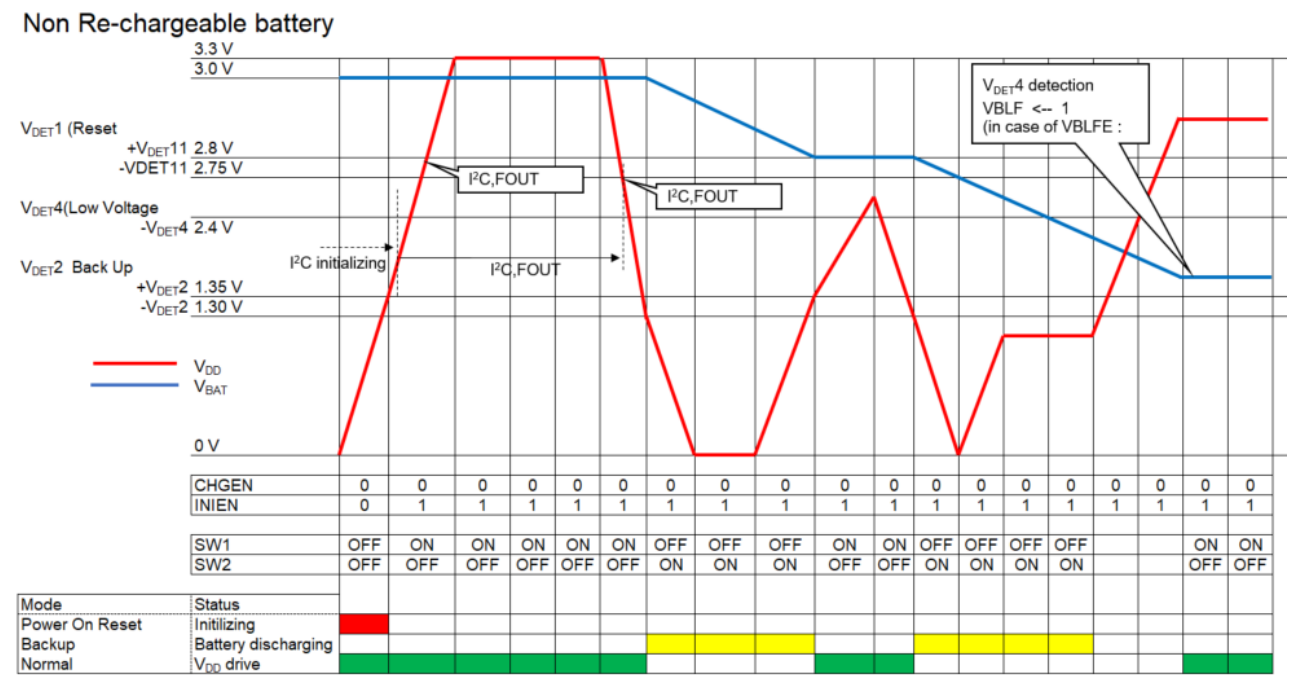
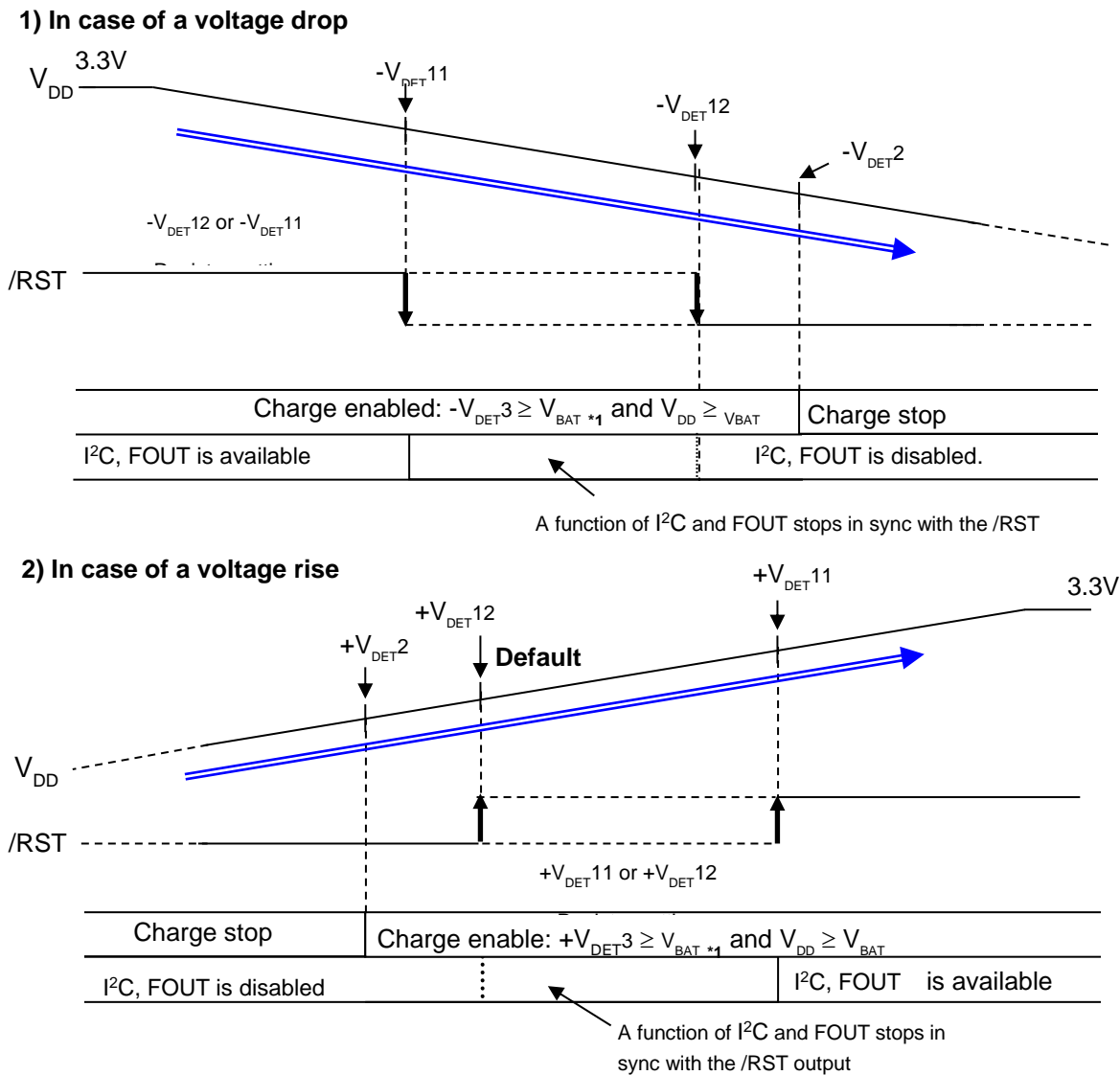


Figure 36 Non re-chargeable battery operation

15.8 Main power supply (V_{DD}) voltage and operation state (INIEN bit = 1)



When full charge detection was deactivated (V_{DET3}) by register setting, V_{BAT} is only charged if V_{DD}

Figure 37 I²C, FOUT operation during voltage drop and rise

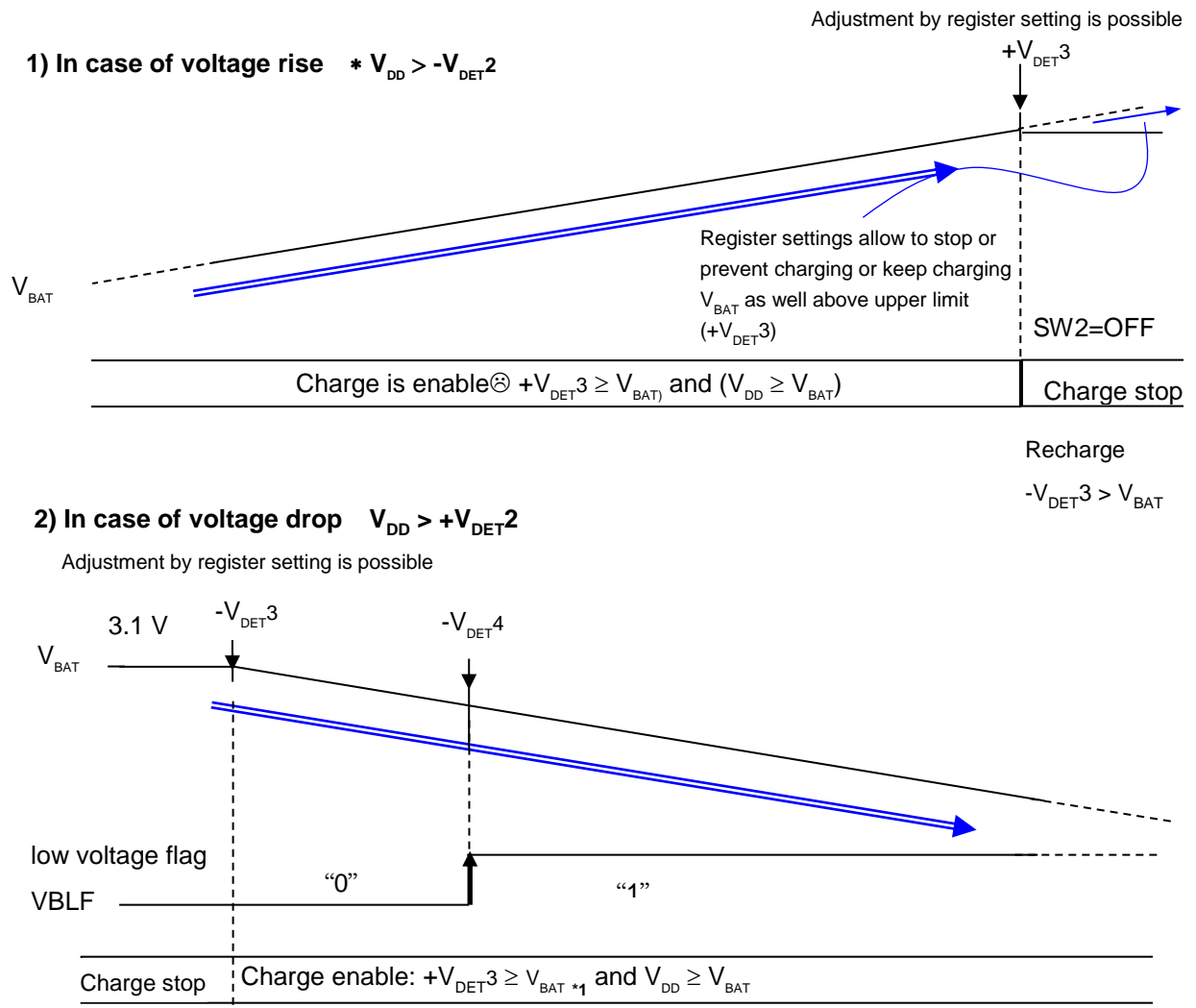
15.9. Backup power supply (V_{BAT}) voltage and a charge state

Figure 38 Re-chargeable battery operation during voltage rise and down

16. Reset output function

This RTC has a built-in Reset-Controller, which outputs a Reset-signal on the /RST-pin to control external HW like MCUs in case of a drop in supply voltage. When the V_{DD} voltage drops below V_{DET1} (register selectable V_{DET11} or V_{DET12}), a /RST-signal is output. Once V_{DD} raises beyond V_{DET1} voltage again, the /RST-signal is released. In case INIEN bit is set to "1", I²C and FOUT are stopped when V_{DD} drops below V_{DET1} .

14.8.1. Related register of reset output function

Address h	Function	bit 7	bit 6	bit 5	bit 4	bit 3	bit 2	bit 1	bit 0
1D	Flag Register	VBLF	0	UF	TF	AF	RSF	VLF	VBFF
1F	Control Register1	SMP TSEL1	SMP TSEL0	CHG EN	INIEN	0	RS VSEL	BF VSEL1	BF VSEL0

1) RSVSEL-bit

Setting of V_{DET1} voltage level. In case V_{DD} drops below this level, the /RST-signal is output and the I/F and FOUT output are stopped (depending on INIEN-bit setting).

Table 43 RSVSEL

RSVSEL	Data	Description
Write / Read	0	$-V_{DET11}$ (2.75 V) (default)
	1	$-V_{DET12}$ (2.70 V)

2) RSF-bit

This bit holds the result of detecting the reset voltage.

Table 44 RSF bit

RSF	Data	Description
Write	0	The RSF is cleared to 0 and waiting for next low voltage detection.
	1	Invalid (writing a 1 will be ignored)
Read	0	-
	1	A voltage drops below $-V_{DET1}$ was detected.

17. Digital offset function

With this function it is possible to increase or decrease the speed of the time counting and thus put a positive or negative offset to the clock precision. The adjustment range for this offset correction is $+192.3 \times 10^{-6}$ to -195.3×10^{-6} in steps of 3.05×10^{-6} .

17.1. Digital offset register

Address h	Function	bit 7	bit 6	bit 5	bit 4	bit 3	bit 2	bit 1	bit 0
30	Digital offset	DTE	L7	L6	L5	L4	L3	L2	L1

- DTE="1" enables the digital offset function.

When the digital offset function is enabled, the digital offset register digitally offsets the sub-second clocks according to the values set in the digital offset register. This correction of the second time register occurs every 10 seconds and the level of correction depends on the offset required. When outputting a 32.768 kHz signal on FOUT-pin, this function has no influence, since the oscillation frequency of the built-in crystal does not change by using this function. In case of outputting a 1 Hz or 1024 Hz signal on FOUT, the offset correction will cause a certain jitter on the clock signal.

Alarm function as well as the Wakeup Timer function (if source clock lower than 4096 Hz is selected) are affected by this function.

- In order to disable the digital offset function, set to DTE = "0". In this case the L1 to L7 are ignored.

- Below table shows the relationship of the L7~L1 bit and the digital offset value

When the L7 bit = "0", the offset is positive (clock runs faster), when the L7 bit = "1", the offset is negative (the clock runs slower).

Table 45 Digital Adjustment

Digital offset bits							Offset value ($\times 10^{-6}$)
L7	L6	L5	L4	L3	L2	L1	
0	1	1	1	1	1	1	+192.26
0	1	1	1	1	1	0	+189.21
•							•
•							•
0	0	0	0	0	1	0	+6.10
0	0	0	0	0	0	1	+3.05
0	0	0	0	0	0	0	± 0.00
1	1	1	1	1	1	1	-3.05
1	1	1	1	1	1	0	-6.10
•							•
•							•
1	0	0	0	0	0	1	-192.26
1	0	0	0	0	0	0	-195.31

The offset value is calculated on basis of a shift of the built-in crystal frequency.

- How to calculate the offset value

1) When the offset value is positive:

$L[7 \sim 1] = [\text{Offset Value}] / 3.05$ However, decimals are discarded.

Example calculation: When the offset value is $+192 \times 10^{-6}$

$$L[7 \sim 1] = 192.26 / 3.05 = 63 \text{ (Dec)} \\ = 0111111 \text{ (bin) is set.}$$

2) When the offset value is negative:

$L[7 \sim 1] = 128 - [\text{Offset Value}] / 3.05$ However, decimals are discarded.

Example calculation: When the offset value is -158×10^{-6}

$$L[7 \sim 1] = 128 - (158 / 3.05) = 76 \text{ (Dec)} = 1001100 \text{ (bin) is set.}$$

3) When calculate from accuracy of a clock

To adjust 30 seconds in 30 days:

Example calculation: $30 \text{ sec.} / 2592000 \text{ s (30 days)} = 11.57 \times 10^{-6}$

Positive offset

$$L[7 \sim 1] = 11.57 / 3.05 = 4 \text{ (Dec)} \text{ However, decimals are discarded.} \\ = 0000100 \text{ (bin) is set.}$$

Negative offset

$$L[7 \sim 1] = 128 - (11.57 / 3.05) = 124 \text{ (Dec)} \text{ However, decimals are discarded.} \\ = 1111100 \text{ (bin) is set.}$$

17.2. Effect of the digital offset function to other functions

Because this function adjusts an internal sub-second clock, this function affects the a Wakeup timer interrupt function and FOUT function

1) FOUT function

- 1 Hz setting: Once in 10 seconds, the 1 Hz period fluctuates.
- 1024 Hz setting: Once in 10 seconds, the 1024 Hz period fluctuates.

*There are cases where there is no fluctuation, depending on the offset correction value.

- 32.768 kHz Not affected.

2) Wakeup timer interrupt function

- 64 Hz or 1 Hz source clock setting: Once in 10 seconds, the period fluctuates.
When the timer intervals are long, the fluctuations appear small.

- 4096 Hz source clock setting: Not affected.

18. Flow-chart

The following flow-chart is one example, but it is not necessarily applicable for every use-case and not necessarily the most effective process for individual applications.

18.1 Initializing example

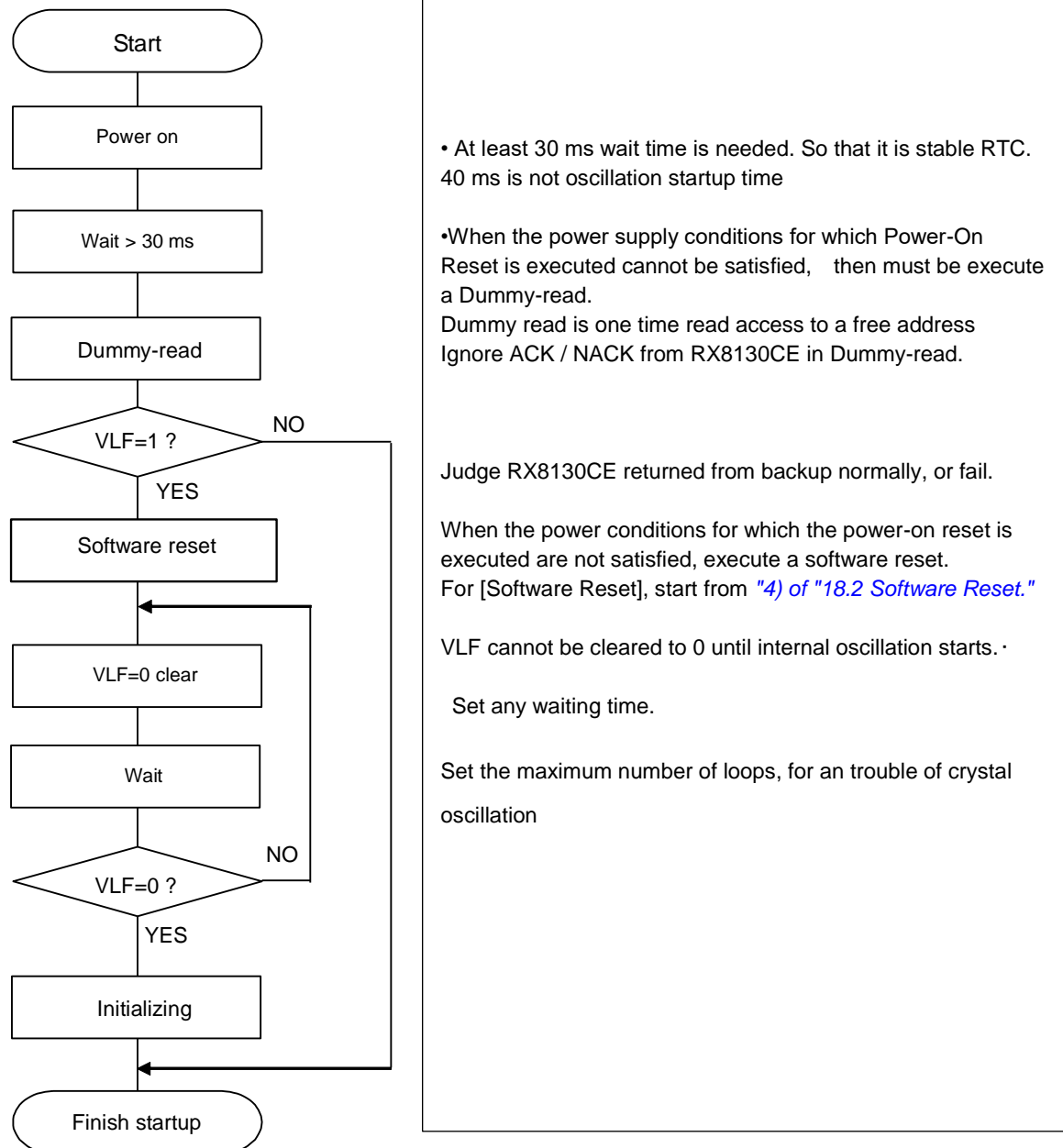


Figure 39 Example flow (Power initialization)

18.2 Software Reset

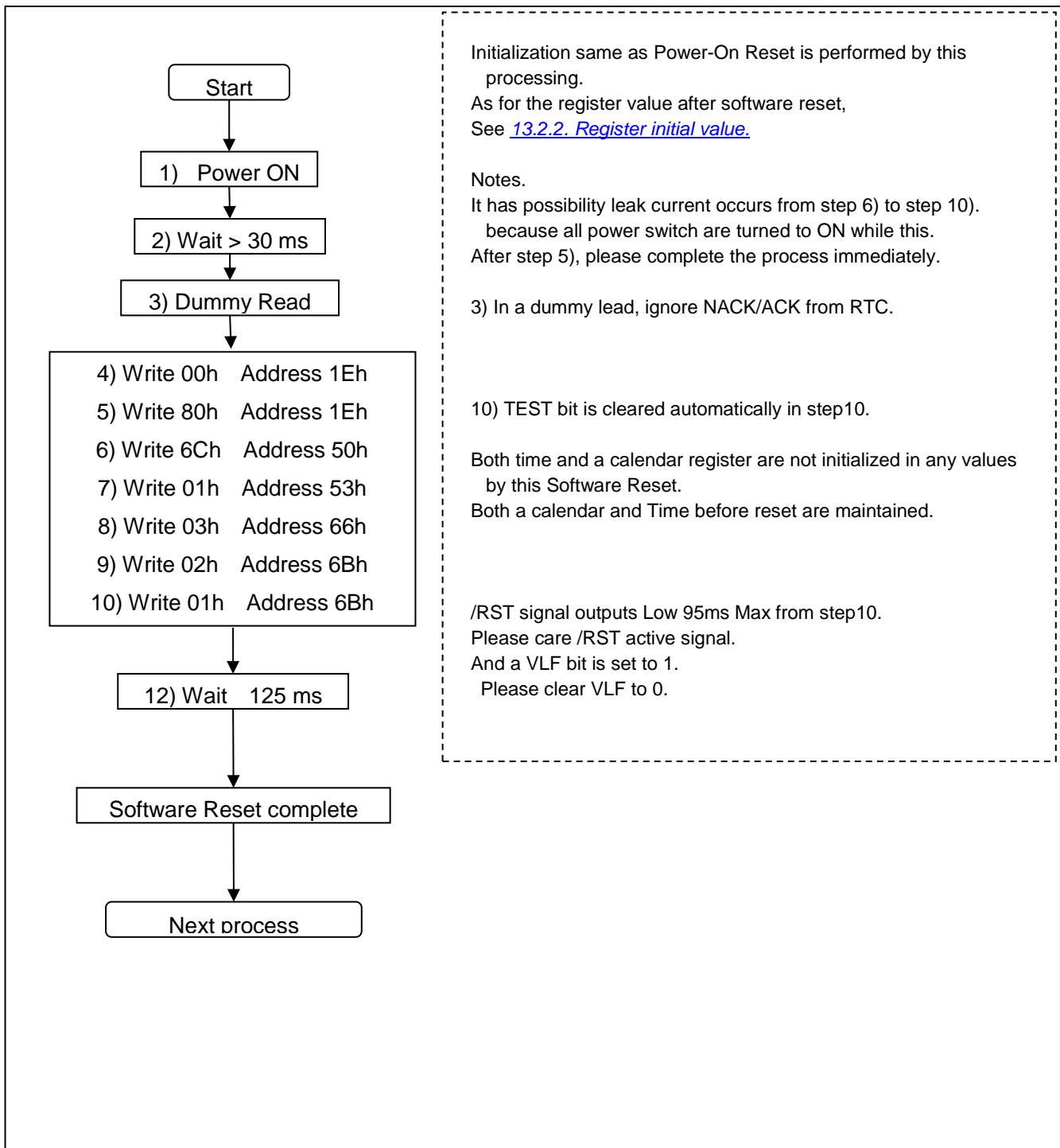


Figure 40 Example Flow(Software Reset)

18.3 Example of Initialization routine

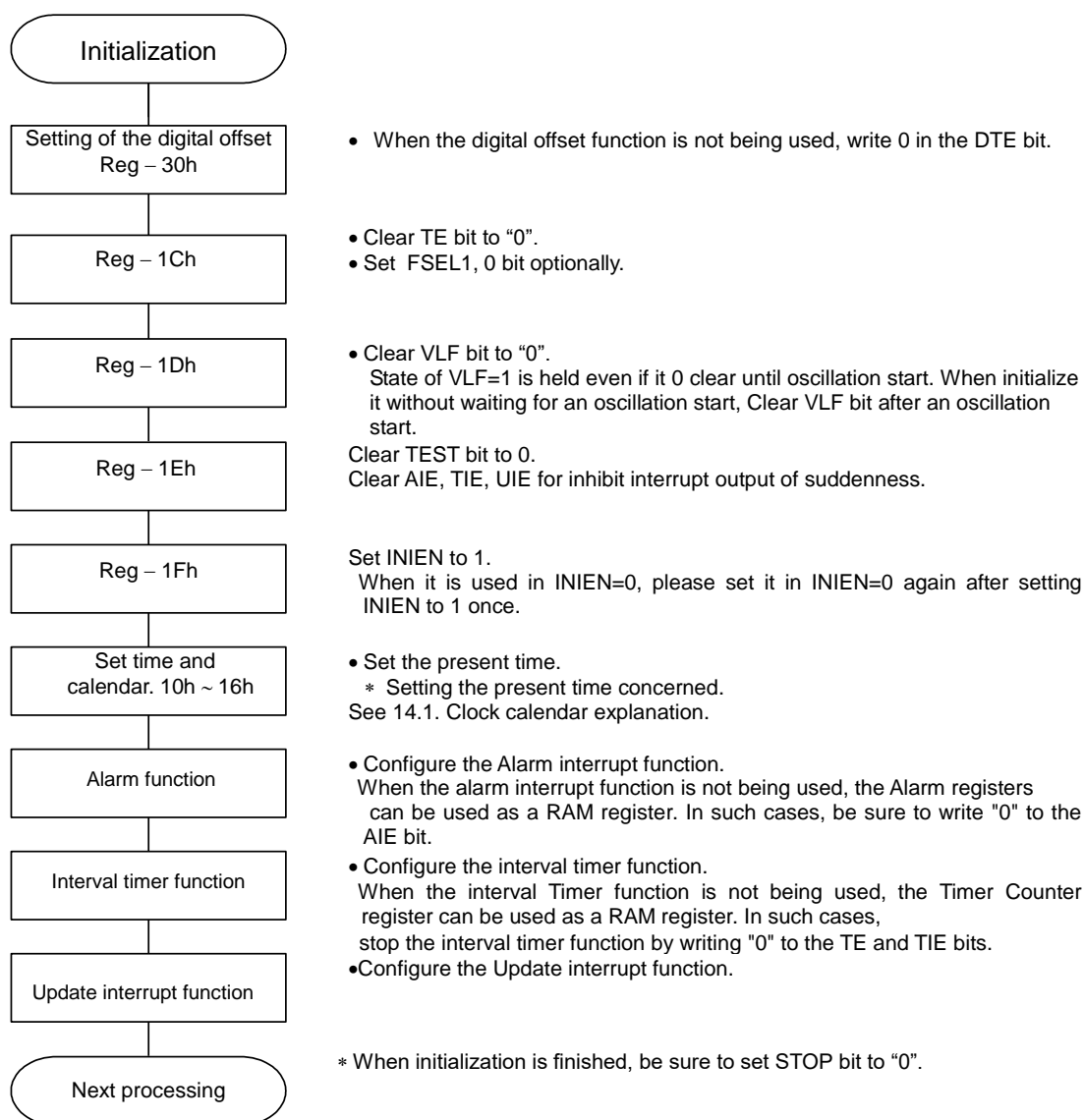


Figure 41 Example flow (Initialization)

18.4 Example of Initialization routine (only clock usage)

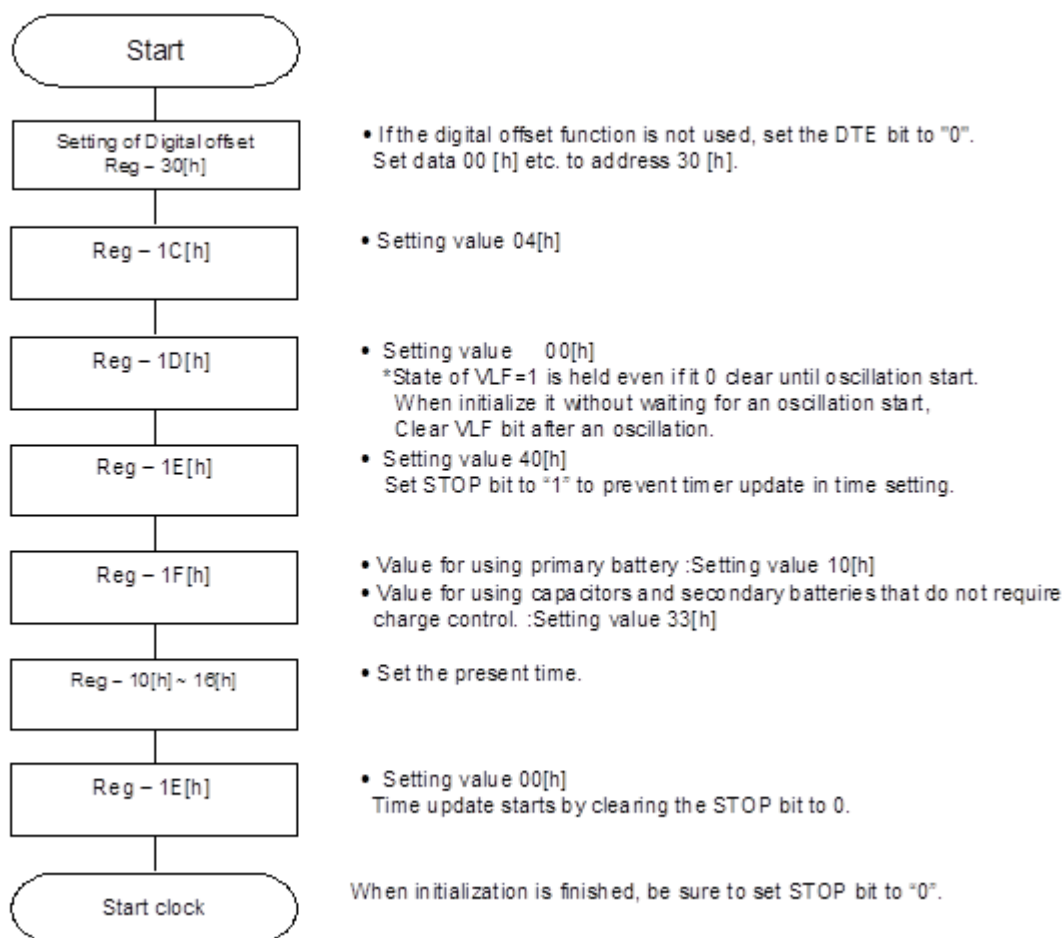


Figure 42 Example flow (initialization only clock usage)

18.5 The setting of the clock and calendar

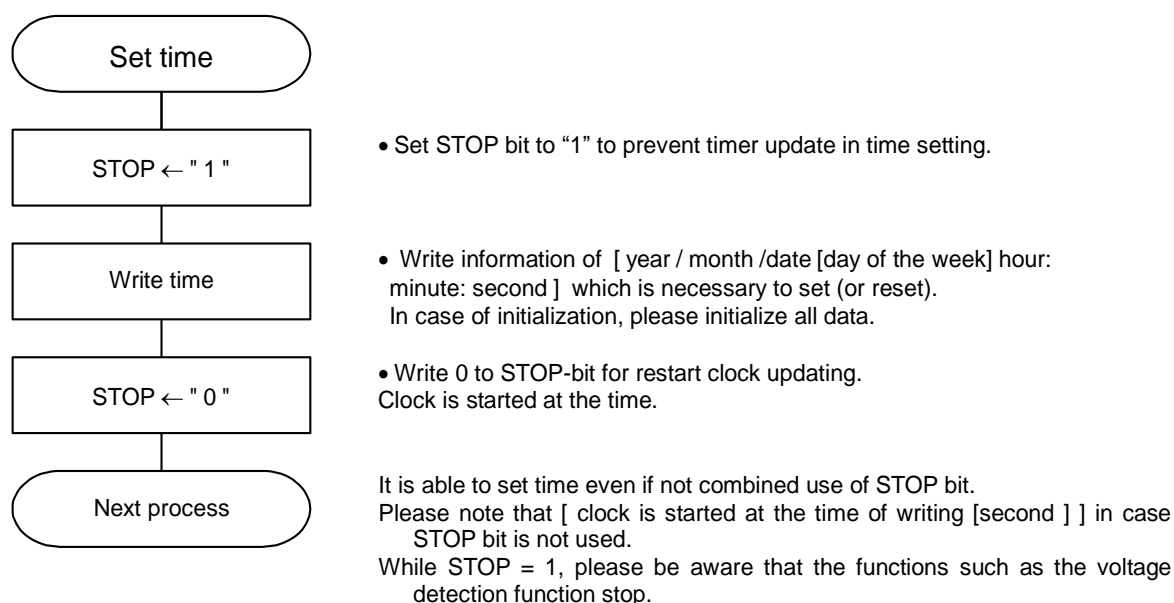


Figure 43 Example flow (Clock, calendar setting)

18.6 The reading of the clock and calendar

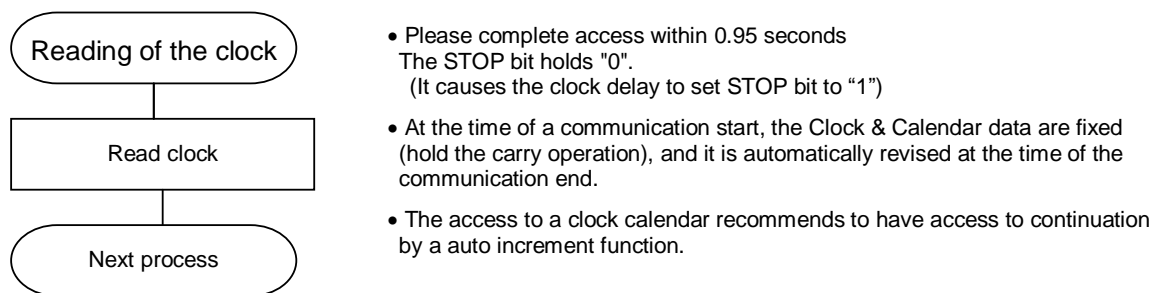


Figure 44 Example flow (Clock, calendar reading)

18.7 Setting example of the wakeup timer interrupt function

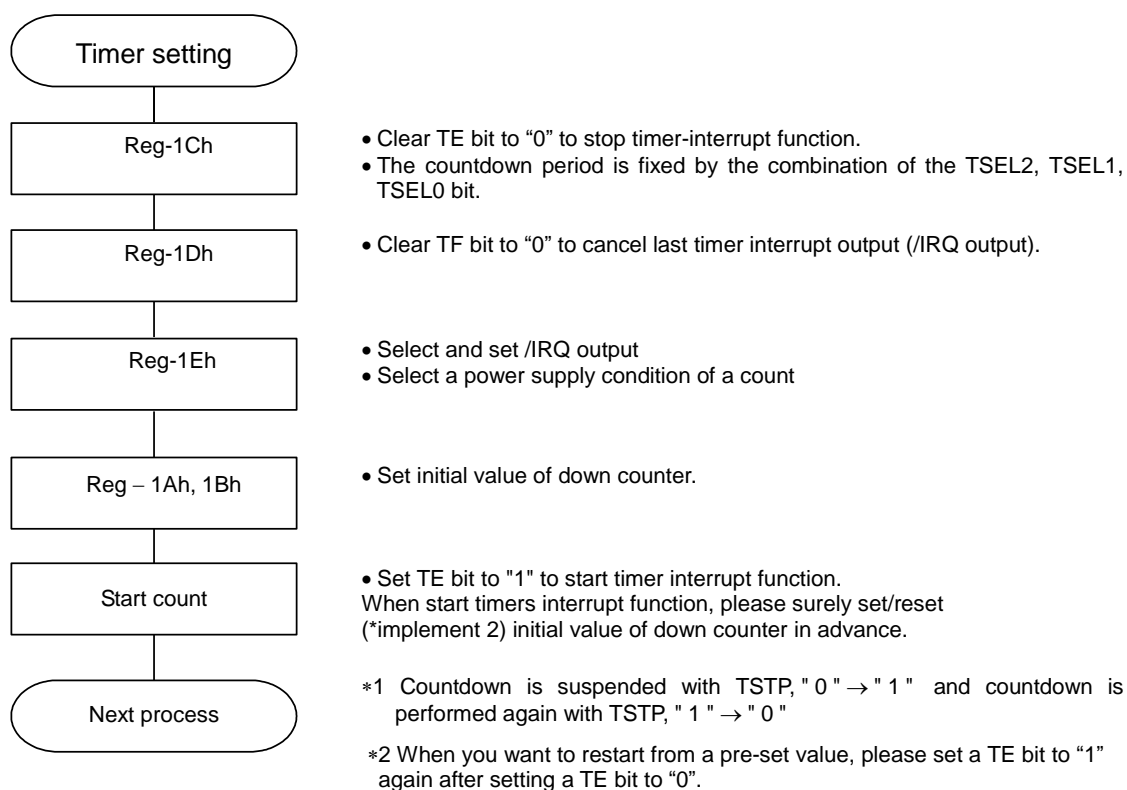
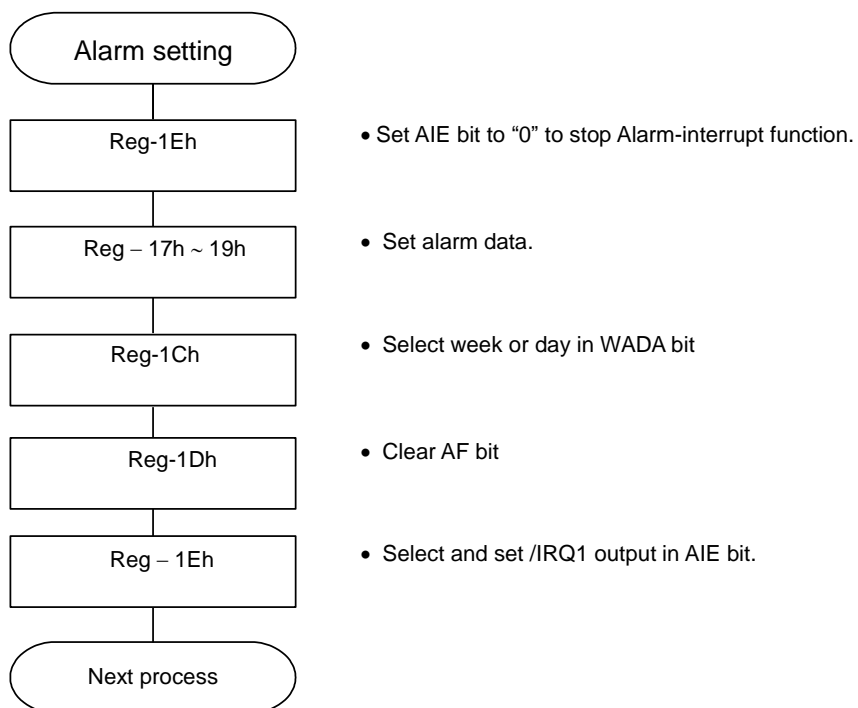


Figure 45 Example flow (Wakeup timer interruption)

18.8 Setting example of the Alarm interrupt function

**Figure 46 Example flow (Alarm interruption)**

19 Serial communication

19.1 Overview of I²C-Bus Interface

The I²C-bus supports bi-directional communications via two signal lines: the SDA (data) line and SCL (clock) line. A combination of these two signals is used to transmit and receive communication start/stop signals, data transfer signals, acknowledge signals, and so on.

Both the SCL and SDA signals are held at high level whenever communications are not being performed.

The starting and stopping of communications is controlled at the rising edge or falling edge of SDA while SCL is at high level.

19.2 Data transfers

Data transfers are performed in 8-bit (1 byte) units once the START condition has occurred. There is no limit on the amount (bytes) of data that are transferred between the START condition and STOP condition.

(However, the transfer time must be no longer than 0.95 seconds.)

19.3 Starting and stopping I²C-Bus communications

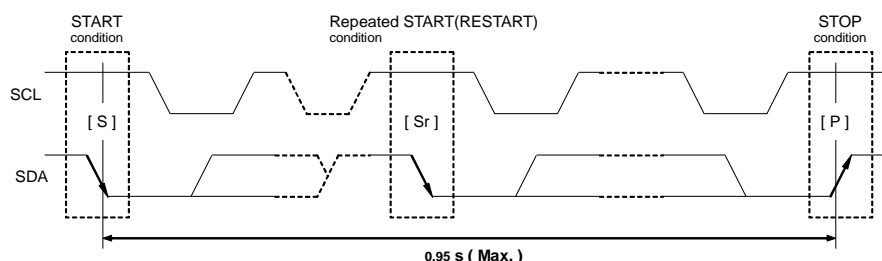


Figure 47 I²C-Bus start/stop timing

1) START condition, repeated START condition, and STOP condition

(1) START condition

- The SDA level changes from high to low while SCL is at high level.

(2) STOP condition

- This condition regulates how communications on the I²C-Bus are terminated. The SDA level changes from low to high while SCL is at high level.

(3) Repeated START condition (RESTART condition)

- In some cases, the START condition occurs between a previous START condition and the next STOP condition, in which case the second START condition is distinguished as a RESTART condition. Since the required status is the same as for the START condition, the SDA level changes from high to low while SCL is at high level.
- When accessing this device, all communication from transmitting the start condition to transmitting the stop condition after access should be completed within 0.95 seconds. If communication requires 0.95 seconds or longer, the I²C bus interface is reset by the internal bus timeout function.

19.4 Slave address

The I²C-Bus devices do not have any chip select or chip enable pins. All I²C-Bus devices are memorized with a fixed unique number in it. The chip selection on the I²C-Bus is executed, when the interface starts, the master device sends the required slave address to all devices on the I²C-Bus. The receiving device only reacts for interfacing, when the required slave address is agreed with its own slave address.

During in actual data transmission, the transmitted data contains the slave address and the data with R/W

Slave address							R/W bit
bit 7	bit 6	bit 5	bit 4	bit 3	bit 2	bit 1	bit 0
0	1	1	0	0	1	0	R/W
0 is Write mode 1 is Read mode							↑

19.5 System configuration

All ports connected to the I²C-Bus must be either open drain or open collector ports in order to enable AND connections to multiple devices.

SCL and SDA are both connected to the VIO line via a pull-up resistance. Consequently, SCL and SDA are both held at high level when the bus is released (when communication is not being performed).

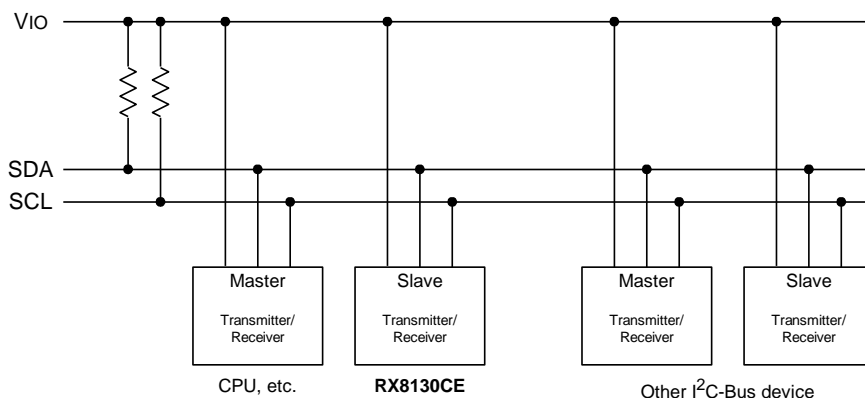


Figure 48 I²C-Bus connection

Any device that controls the data transmission and data reception is defined as a "Master".

and any device that is controlled by a master device is defined as a "Slave".

The device transmitting data is defined as a "Transmitter" and the device receiving data is defined as a receiver"

In the case of this RTC module, controllers such as a CPU are defined as master devices and the RTC module is defined as a slave device. When a device is used for both transmitting and receiving data, it is defined as either a transmitter or receiver depending on these conditions.

19.6 I²C-Bus protocol

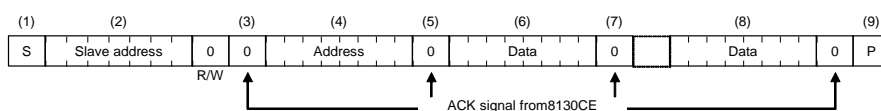
In the following sequence descriptions, it is assumed that the CPU is the master and the RX8130CE is the slave.

1) Address specification write sequence

Since the RX8130CE includes an address auto increment function, once the initial address has been specified, the RX8130 increments (by one byte) the receive address each time data is transferred.

Address circulation of auto increment function.	10h -> 1Fh -> 10h
	20h -> 2Fh -> 20h
	30h -> 3Fh -> 30h

- (1) CPU transfers start condition [S].
- (2) CPU transmits the RX8130CE's slave address with the R/W bit set to write mode.
- (3) Check for ACK signal from RX8130CE.
- (4) CPU transmits write address to RX8130CE.
- (5) Check for ACK signal from RX8130CE.
- (6) CPU transfers write data to the address specified at (4) above.
- (7) Check for ACK signal from RX8130CE.
- (8) Repeat (6) and (7) if necessary. Addresses are automatically incremented.
- (9) CPU transfers stop condition [P].



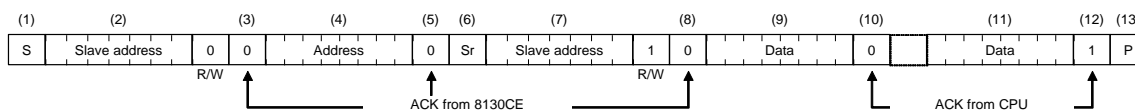
2) Address specification read sequence

After using write mode to write the address to be read, set read mode to read the actual data.

- (1) CPU transfers start condition [S].
- (2) CPU transmits the RX8130CE's slave address with the R/W bit set to write mode.
- (3) Check for ACK signal from RX8130CE.
- (4) CPU transfers address for reading from RX8130CE.
- (5) Check for ACK signal from RX8130CE.
- (6) CPU transfers RESTART condition [Sr] (in which case, CPU does not transfer a STOP condition [P]).
- (7) CPU transfers RX8130CE's slave address with the R/W bit set to read mode.
- (8) Check for ACK signal from RX8130CE (from this point on, the CPU is the receiver and the RX8130 is the transmitter).
- (9) Data from address specified at (4) above is output by the RX8130.
- (10) CPU transfers ACK signal to RX8130CE.
- (11) Repeat (9) and (10) if necessary. Read addresses are automatically incremented.

(12) CPU transfers ACK signal for "1".

(13) CPU transfers stop condition [P].



3) Read sequence when address is not specified

Once read mode has been initially set, data can be read immediately. In such cases, the address for each read operation is the previously accessed address + 1.

(1) CPU transfers start condition [S].

(2) CPU transmits the RX8130CE's slave address with the R/W bit set to read mode.

(3) Check for ACK signal from RX8130CE (from this point on, the CPU is the receiver and the RX8130CE is the transmitter).

(4) Data is output from the RX8130 to the address following the end of the previously accessed address.

(5) CPU transfers ACK signal to RX8130CE.

(6) Repeat (4) and (5) if necessary. Read addresses are automatically incremented in the RX8130.

(7) CPU transfers ACK signal for "1".

(8) CPU transfers stop condition [P].

20 Circuit Diagram connection

20.1 Typical MCU connection

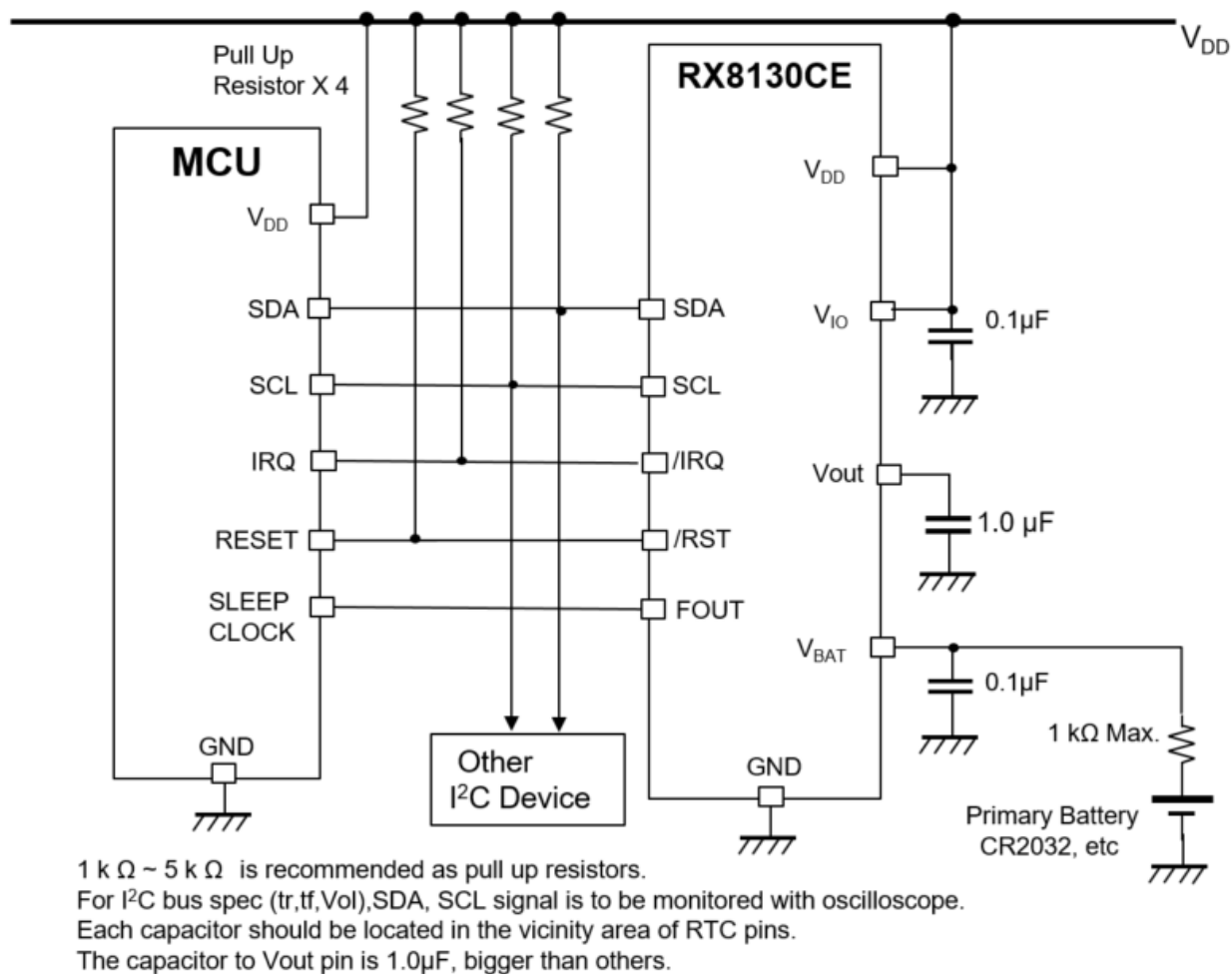


Figure 49 Typical MCU connection

20.2 32.768 kHz oscillator application connection

See also [14.6. FOUT function](#)

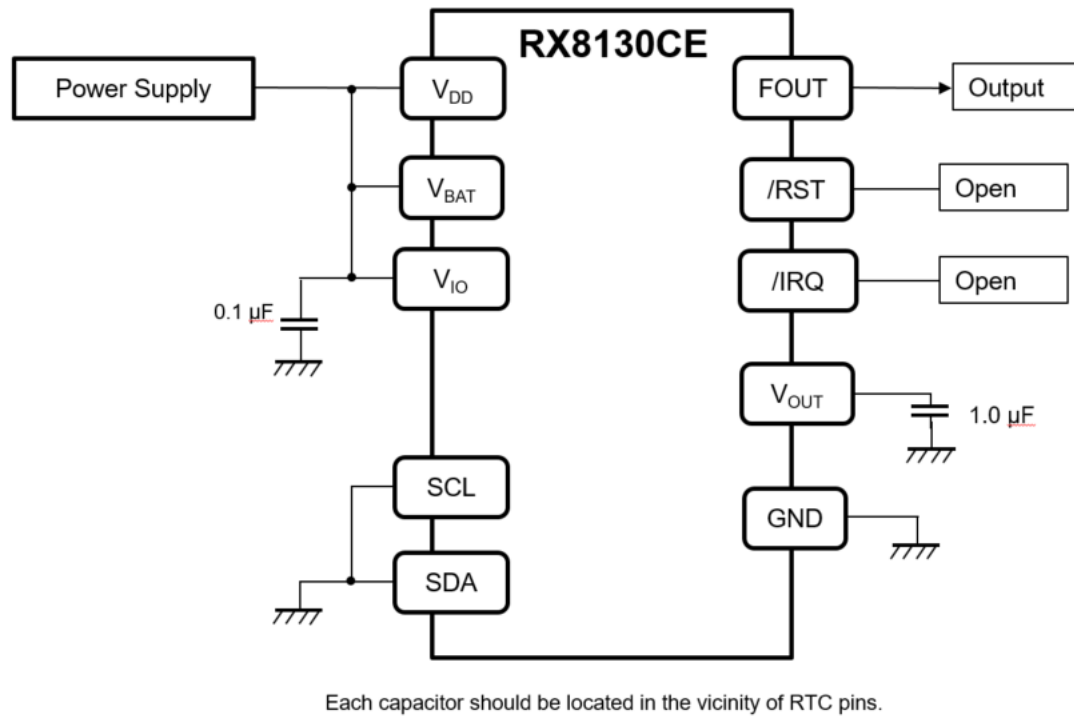


Figure 50 32.768 kHz oscillator connection

21. Tables

Table 1 Pin Description.....	7
Table 2 Absolute Maximum Rating.....	10
Table 3 Recommended Operation Condition	10
Table 4 Frequency Characteristics	10
Table 5 DC characteristics (1)	11
Table 6 DC characteristics(2)	12
Table 7 AC characteristics.....	13
Table 8 AC characteristics (FOUT).....	13
Table 9 AC Characteristics (Reset)	14
Table 10 Reset timing	14
Table 11 Power supply characteristics	16
Table 12 Register Table.....	20
Table 13 Register initial value, Read/Write	21
Table 14 Time, calendar setting example (Sun, 29-Feb-88 17:39:45 (leap year)).....	24
Table 15 Setting example of the week register value.....	25
Table 16 Countdown period (source clock) selection.....	26
Table 17 Wakeup timer control.....	27
Table 18 Wakeup timer interrupt detection flag.....	28
Table 19 Wakeup timer interrupt control	28
Table 20 Wakeup timer normal mode/backup mode control.....	28
Table 21 Wakeup timer stop control.....	28
Table 22 Wakeup timer interrupt cycles	30
Table 23 WEEK/DAY control	33
Table 24 Alarm Flag.....	33
Table 25 Alarm Interrupt control	33
Table 26 WEEK alarm example.....	33
Table 27 DAY alarm example.....	34
Table 28 Second/Minute selection	35
Table 29 Time update Flag.....	35
Table 30 Time update interrupt control.....	35
Table 31 Oscillation stop detection flag.....	37
Table 32 FOUT Frequency selection.....	37
Table 33 Reference characteristics of switching elements.....	38
Table 34 CHGEN bit	40
Table 35 INIEN bit.....	40
Table 36 Voltage detection timing	43
Table 37 VDET3, VDET4 intermittent detection period.....	43
Table 38 VDET1,VDET2,VDET3,VDET4 setting	45
Table 39 BFVSEL1, BFVSEL0	45

Table 40 VBFF	46
Table 41 VBLF	46
Table 42 VBLFE	46
Table 43 RSVSEL	50
Table 44 RSF bit	50
Table 45 Digital Adjustment	51

22. Figures

Figure 1 Block Diagram	6
Figure 2 Package	7
Figure 3 Circuit EX1	8
Figure 4 Circuit EX2	8
Figure 5 Circuit EX3	8
Figure 6 Circuit EX4	8
Figure 7 External Dimension and Soldering pattern	9
Figure 8 Marking Layout	9
Figure 9 I ² C-Bus Interface Timing Chart	13
Figure 10 Reset signal timing chart (Power Initial Supply)	14
Figure 11 Reset signal timing chart (Backup resume)	14
Figure 12 Power supply initial sequence	15
Figure 13 Power-On sequence1	16
Figure 14 Power-On sequence2	16
Figure 15 Frequency temperature characteristics	17
Figure 16 Basic (32.768 k Hz oscillation, counter, FOUT) Function	24
Figure 17 Wakeup timer initial sequence	27
Figure 18 Wakeup timer block diagram	27
Figure 19 Wakeup timer start sequence	29
Figure 20 Wakeup timer inner block diagram	30
Figure 21 Wakeup timer timing chart	31
Figure 22 Alarm interrupt inner block diagram	34
Figure 23 Alarm Interrupt time chart	34
Figure 24 Time update inner block diagram	36
Figure 25 Time update time chart	36
Figure 26 Battery backup switchover block diagram	38
Figure 27 V _{BAT} charge current characteristics V _{DD} = 3.0 V, 5.5 V	39
Figure 28 Re-chargeable battery connection	39
Figure 29 Non re-chargeable battery SW1, SW2 control (INIEN:1, CHGEN:0)	40
Figure 30 Non Re-chargeable battery SW1, SW2 control (INIEN = 1, CHGEN = 0)	40
Figure 31 Re-chargeable battery SW1, SW2 control (INIEN = 1, CHGEN = 1)	41
Figure 32 Battery backup (SW1, SW2 automatic control)	42

Figure 33 V _{DD} detection (VDET2) timing	44
Figure 34 VDET3, VDET4 voltage detection timing) BFMSEL1, BFMSEL0 bit	45
Figure 35 Re-chargeable battery operation.....	47
Figure 36 Non re-chargeable battery operation	47
Figure 37 I ² C, FOUT operation during voltage drop and rise.....	48
Figure 38 Re-chargeable battery operation during voltage rise and down	49
Figure 39 Example flow (Power initialization).....	53
Figure 40 Example Flow(Software Reset).....	54
Figure 41 Example flow (Initialization)	55
Figure 42 Example flow (initialization only clock usage)	56
Figure 43 Example flow (Clock, calendar setting)	56
Figure 44 Example flow (Clock, calendar reading).....	57
Figure 45 Example flow (Wakeup timer interruption)	57
Figure 46 Example flow (Alarm interruption)	58
Figure 47 I ² C-Bus start/stop timing	59
Figure 48 I ² C-Bus connection.....	60
Figure 49 Typical MCU connection.....	63
Figure 50 32.768 kHz oscillator connection.....	64

Application Manual
Real Time Clock Module
RX8130CE



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